

Silicon Photonics

Opportunity, applications
& Recent Results



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www.intel.com/go/sp

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Agenda

- Motivation & applications
- History & progress
- Intel's Research Program
- Future work
- Summary

Photonics Applications



Enterprise
Communication

Wireless RF
Distribution



PC, Server
Interconnects



Health

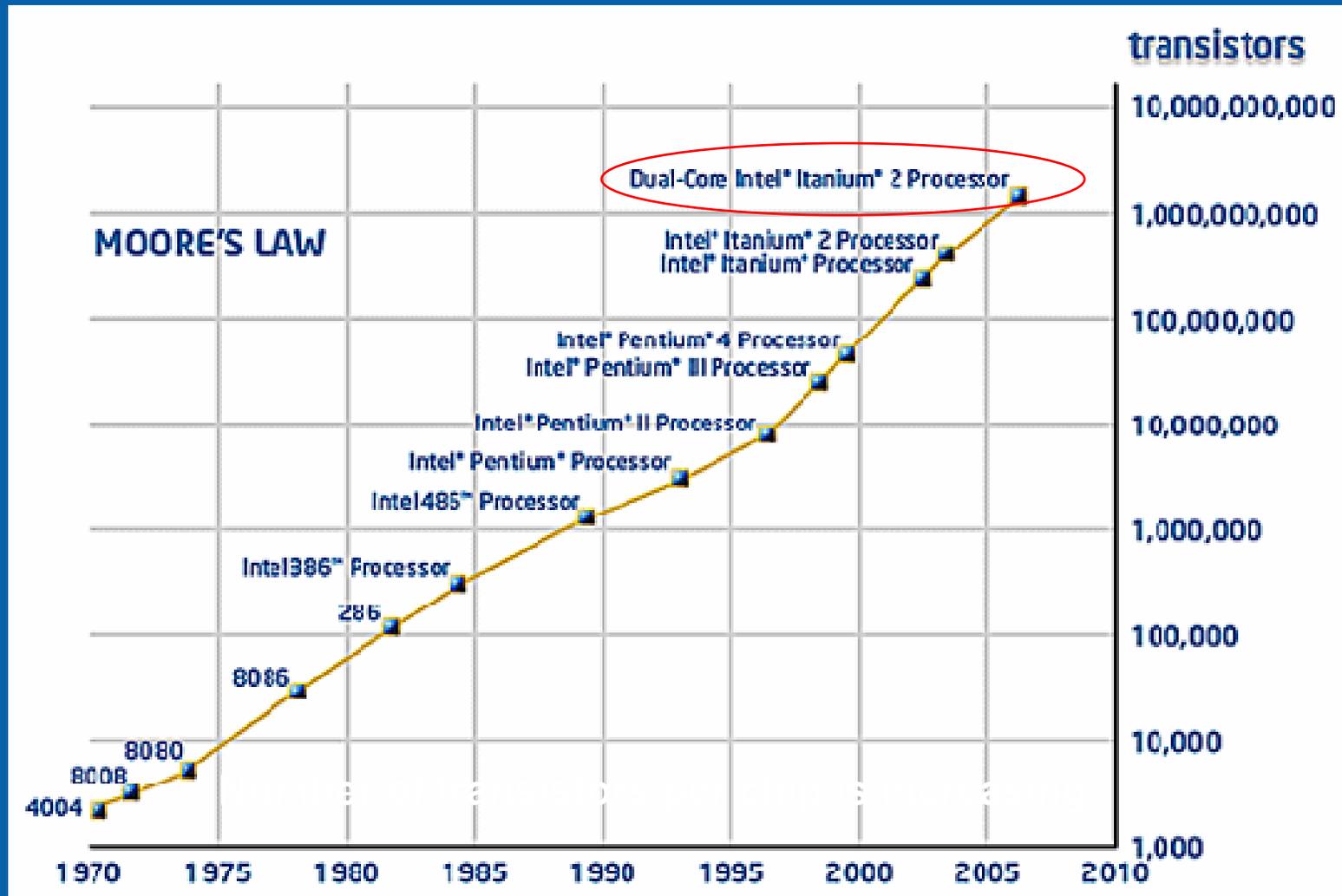
Chemical
Analysis



Environmental
Monitoring

Photonics could impact all of these.
But today costs are prohibitive.

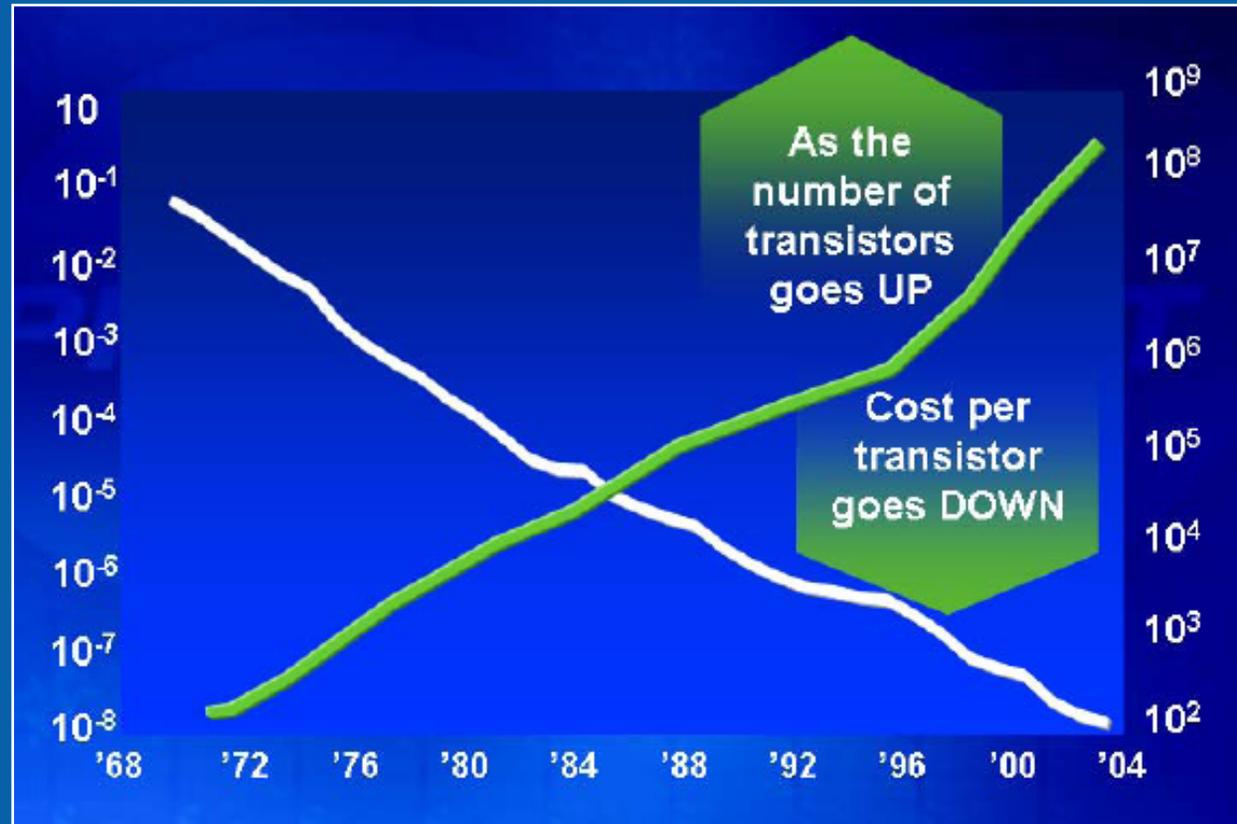
Processor History



Intel co-founder G. Moore predicted doubling of transistors approximately every 2 years (*Electronic Magazine, 1965*)

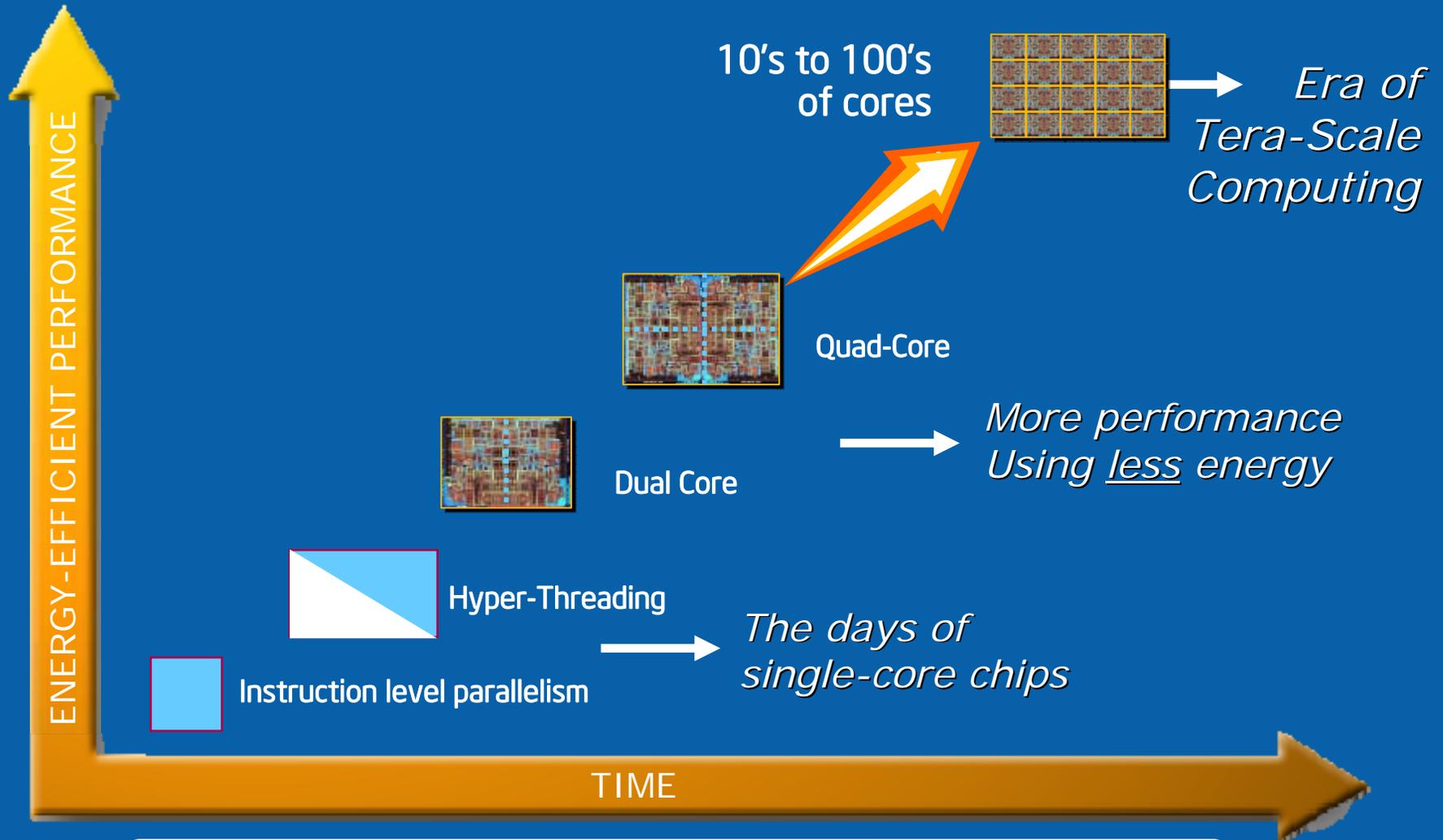
Electronics: Economics of Moore's Law

SCALING + WAFER SIZE + HIGH VOLUME = LOWER COST



Integration & increased functionality

Tera-leap to Parallelism:



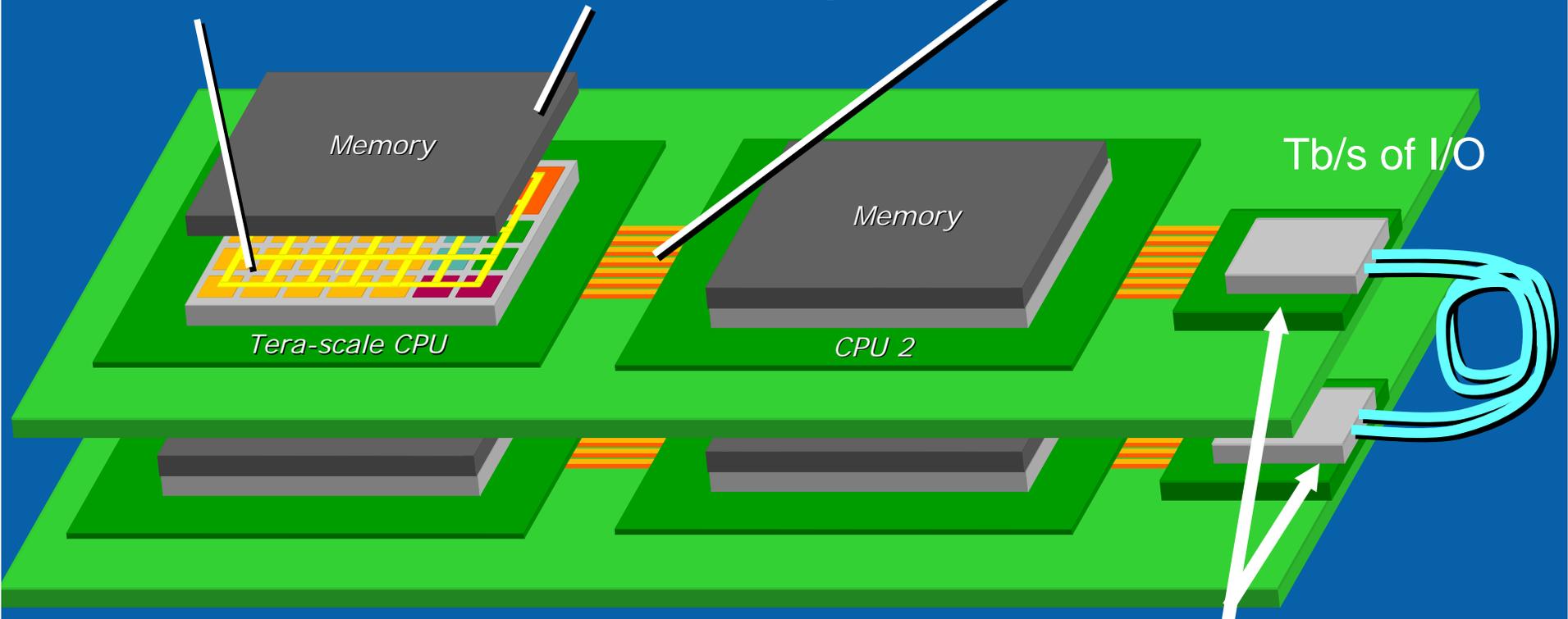
All this compute capability may require high speed optical links

Future Physical I/O for a Tera-scale Servers

Core-Core: On Die Interconnect fabric

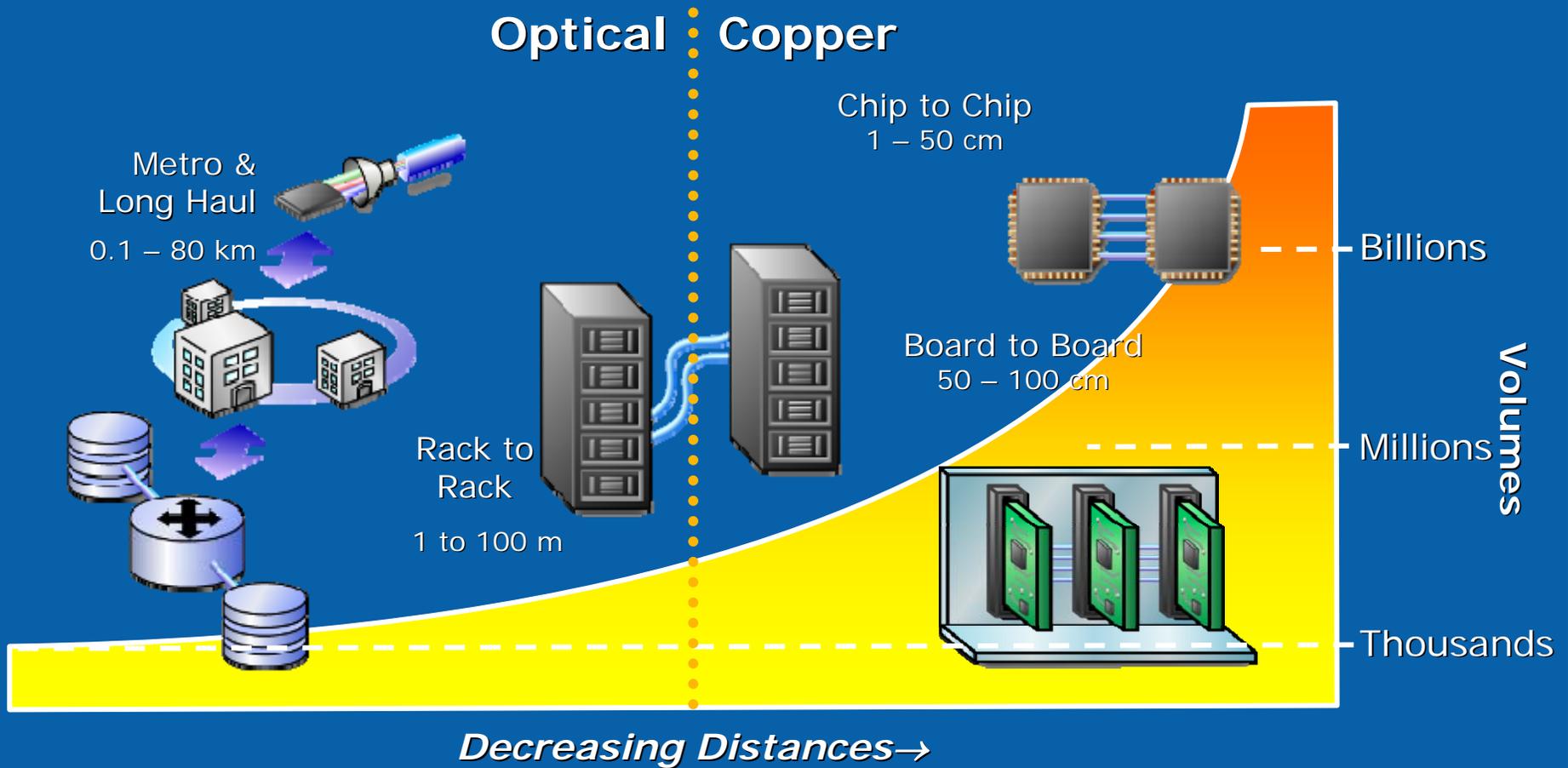
Memory: Package 3D Stacking

Chip-Chip: Fast Copper FR4 or Flex cables



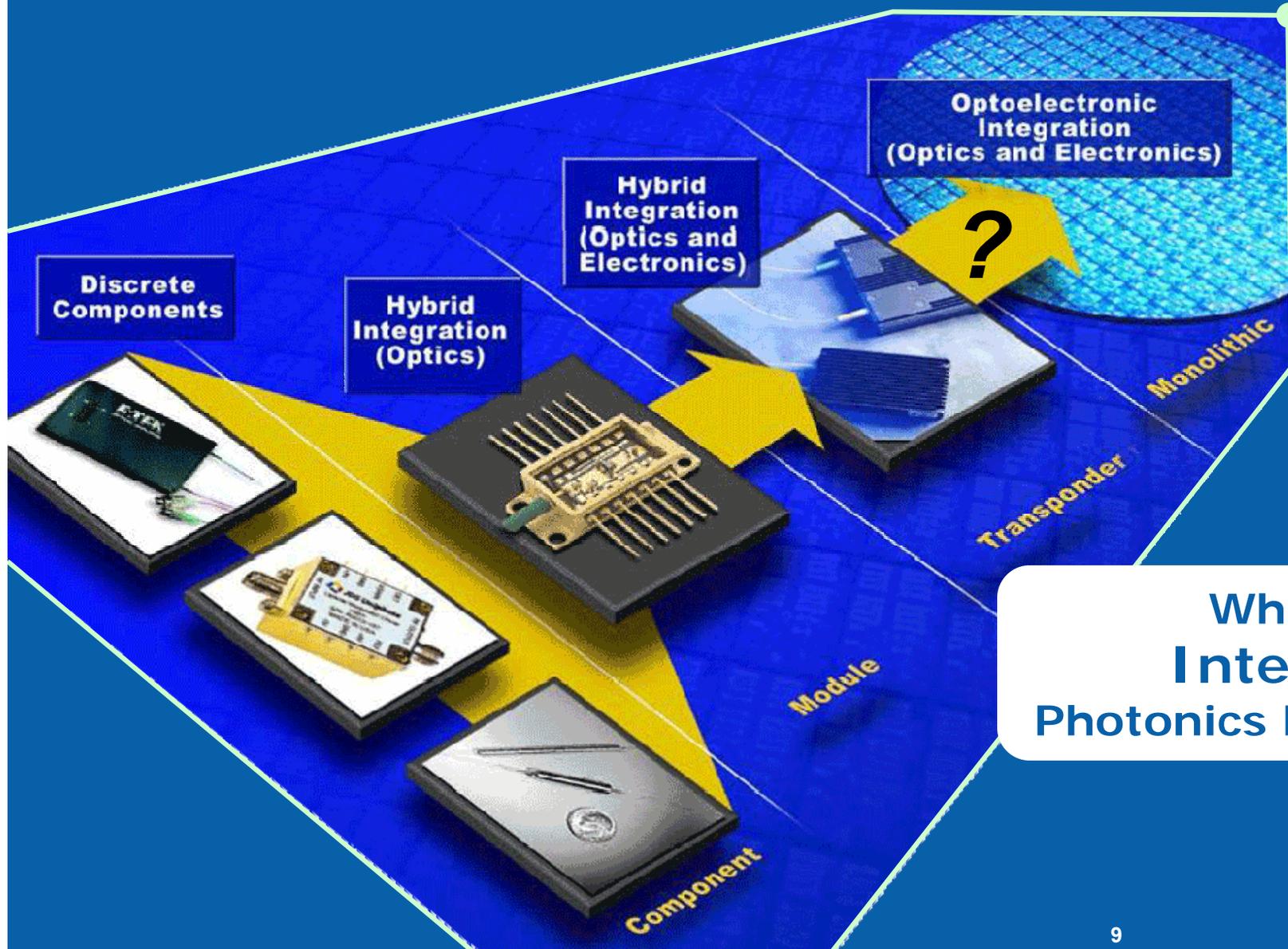
Integrated Tb/s Optical Chip?

Moving to Interconnects



Drive optical to high volumes and low costs

Photonics Evolution



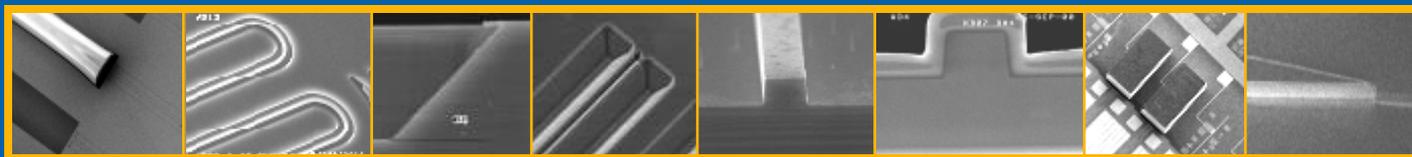
A microscopic view of silicon photonic components, showing a dark, rectangular chip with intricate patterns of light-colored material. The chip is surrounded by a dense field of small, yellowish, crystalline particles. A thin, multi-colored fiber optic cable is visible on the left side of the chip.

Silicon Photonics

- Motivation & applications
- History & progress
- Intel's Research Program
- Future work
- Summary

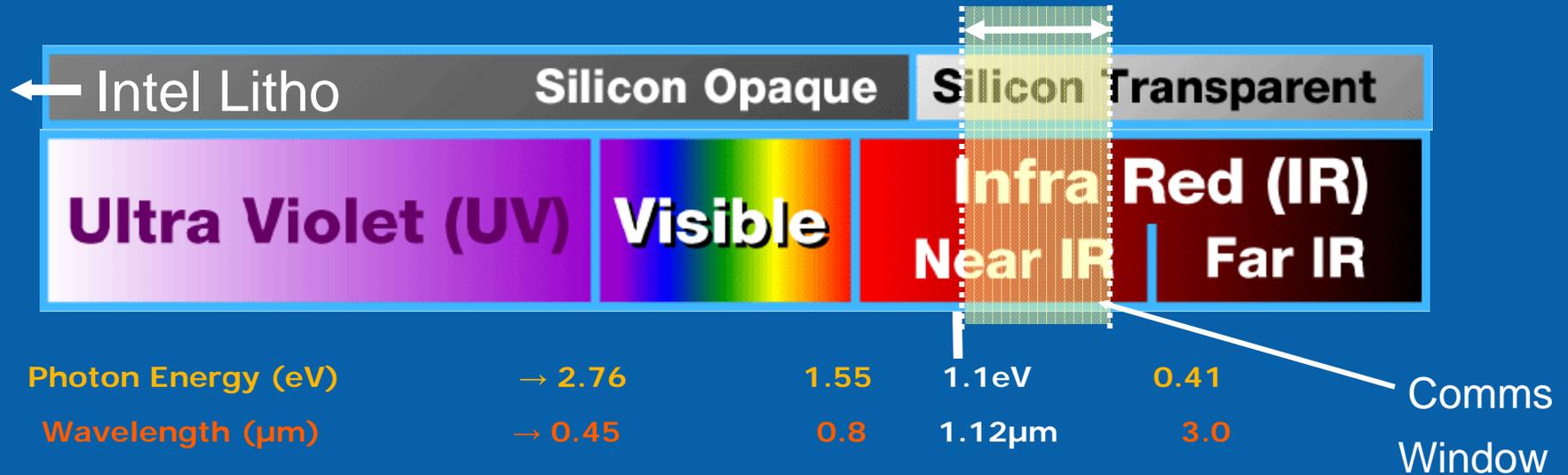
The Opportunity of Silicon Photonics

- Enormous (\$ billions) CMOS infrastructure, process learning, and capacity
 - Draft continued investment in Moore's law
- Potential to integrate multiple optical devices
- Micromachining could provide smart packaging
- Potential to converge computing & communications



**To benefit from this optical wafers
must run alongside existing product.**

Silicon as an Optical Material



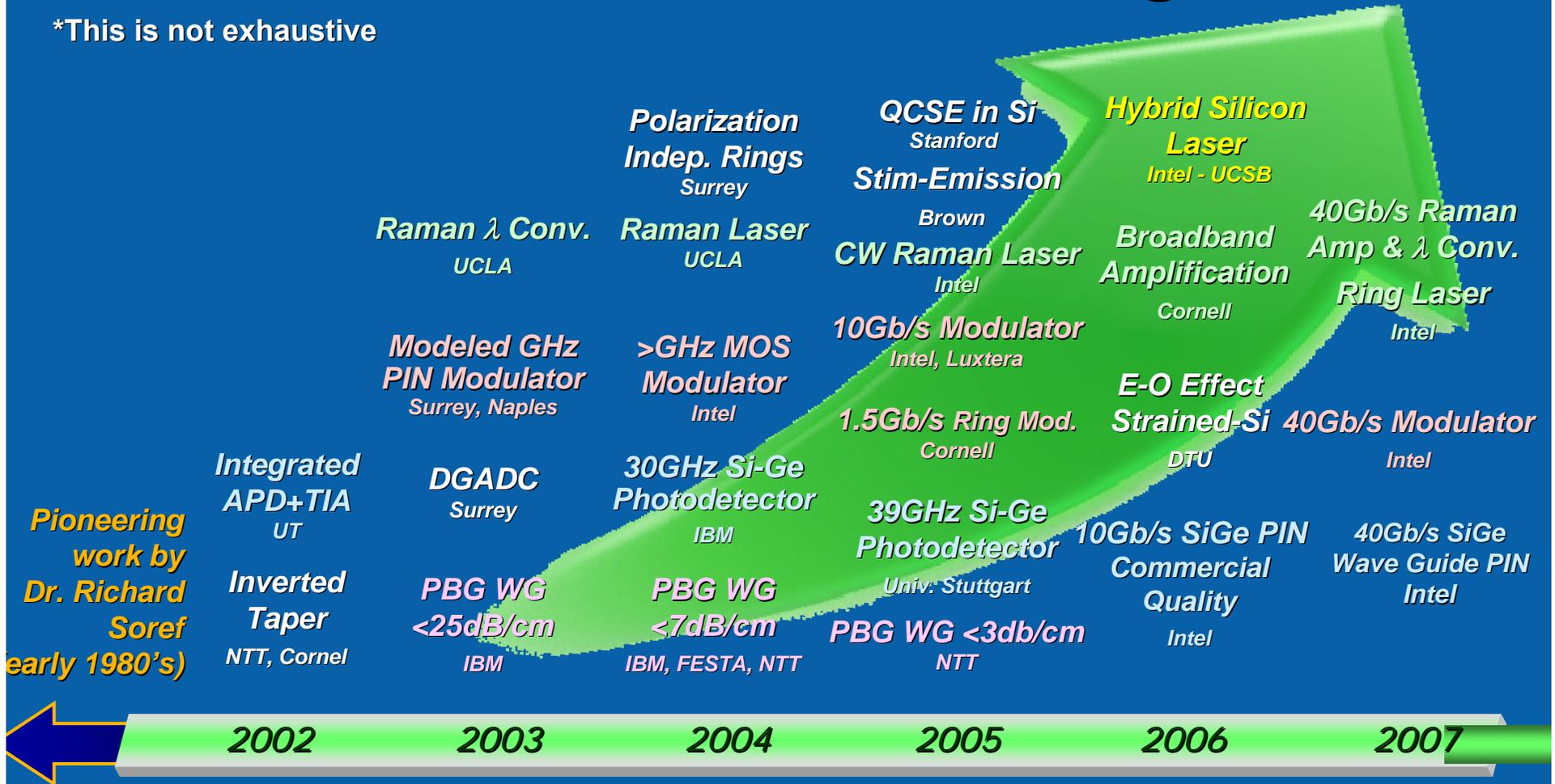
- ✓ Transparent > ~1.1 μm
- ✓ High index
- ✓ CMOS Compatible
- ✓ Low cost material

- ☹ Low light emission efficiency
- ☹ No electro-optical effect
- ☹ No detection in 1.3-1.6 μm

Silicon traditionally NOT optical material of choice

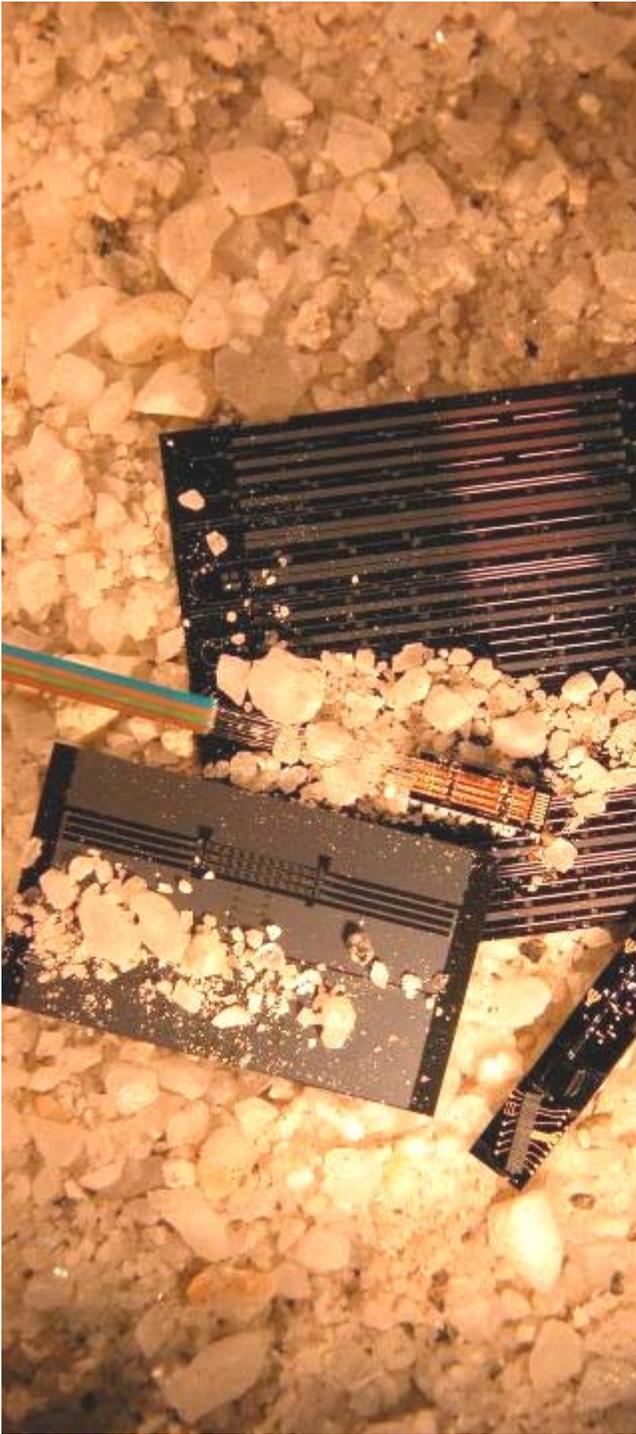
Si Photonics Recent Progress

*This is not exhaustive



Device performance making significant advances

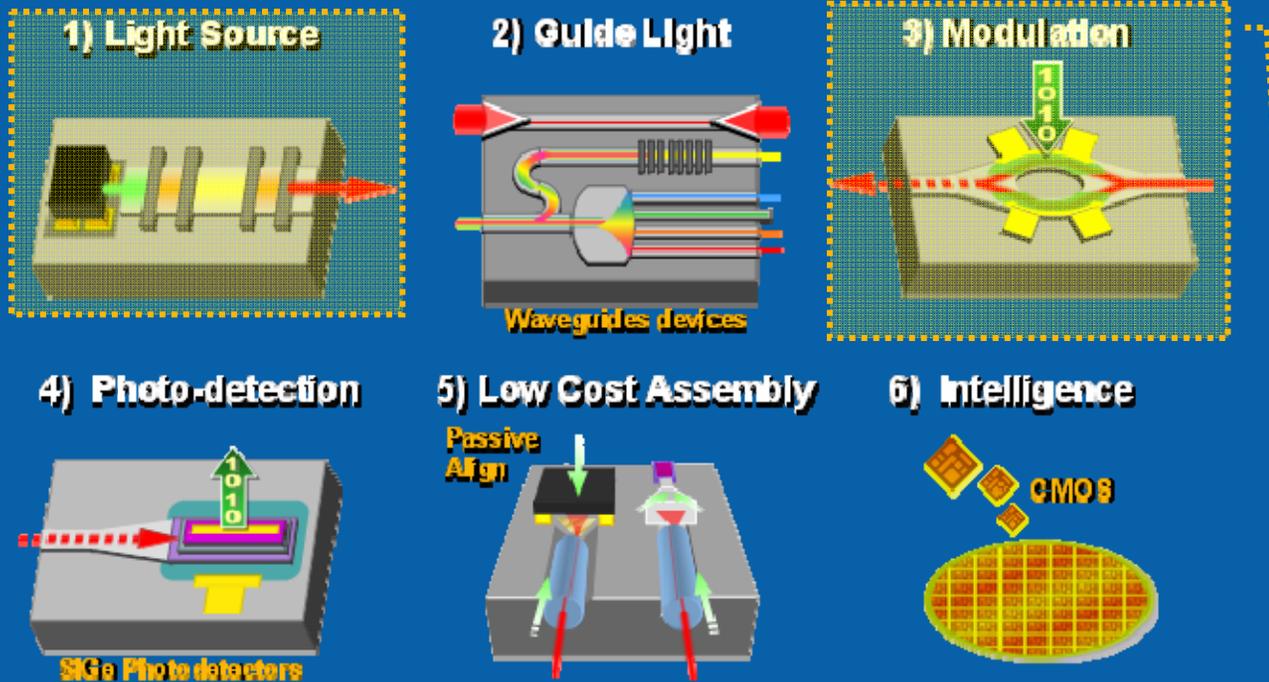


A microscopic view of silicon photonic components, showing a dark, rectangular chip with intricate patterns of lines and structures. The chip is surrounded by a dense field of small, yellowish, crystalline particles, likely silicon or silicon dioxide. The background is a textured, orange-brown surface.

Silicon Photonics

- Motivation & applications
- History & progress
- Intel's Research Program
- Future Work
- Summary

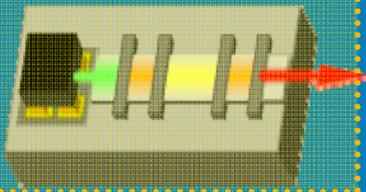
Intel's Silicon Photonics Research



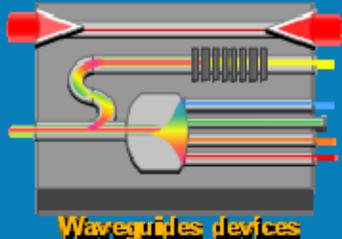
First: Innovate to prove silicon is a viable optical material

Intel's Silicon Photonics Research

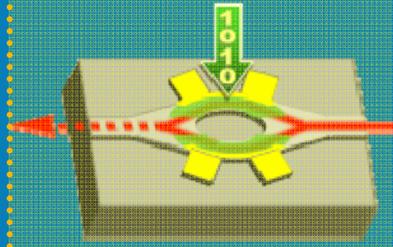
1) Light Source



2) Guide Light



3) Modulation

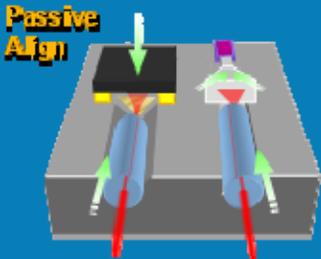


Continuous Wave Silicon Raman Laser
(Feb '05)

4) Photo-detection



5) Low Cost Assembly



6) Intelligence



1GHz (Feb '04)
10 Gb/s (Apr '05)

Electrically Pumped Hybrid Silicon laser
(September 2006)

40 Gb/s TODAY

40 Gb/s (Jul '07)

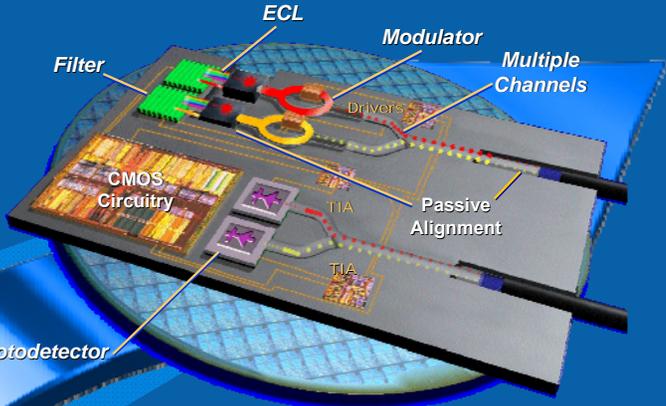
Achieved 40 Gb/s for most devices
Next: Focus on integration



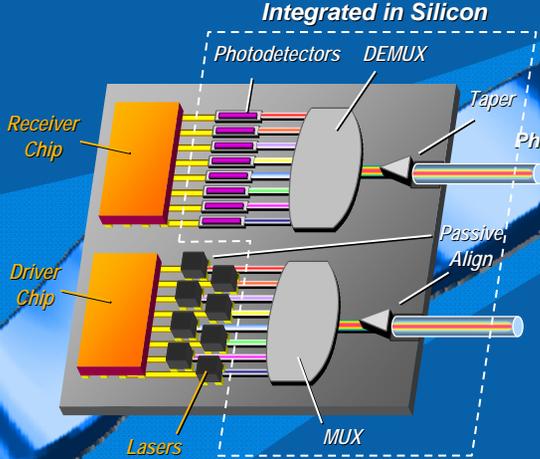
Integration Vision

Time 

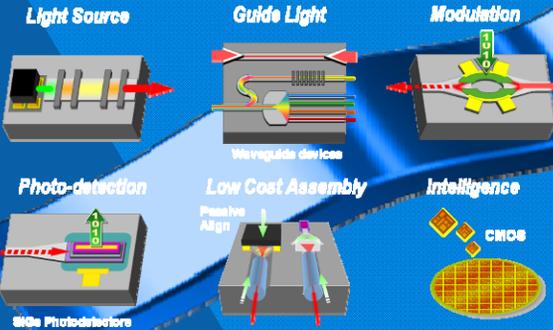
First: Prove Silicon good optical material



FUTURE Monolithic?



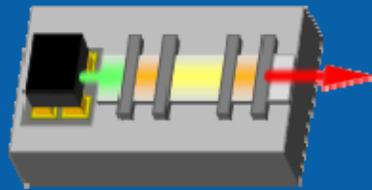
Next Integration: silicon devices into hybrid modules



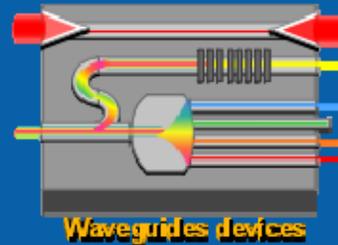
Increasing silicon integration over time

Building Block Research

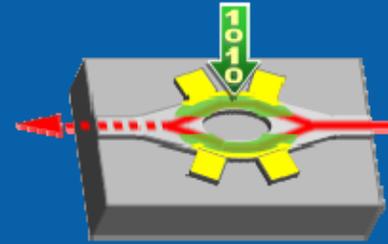
1) Light Source



2) Guide Light



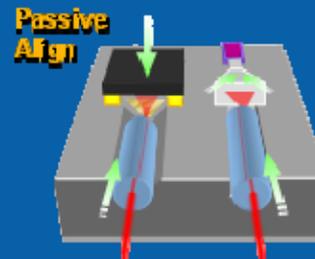
3) Modulation



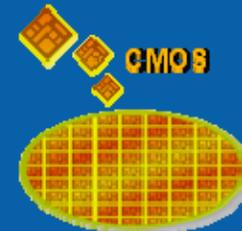
4) Photo-detection



5) Low Cost Assembly

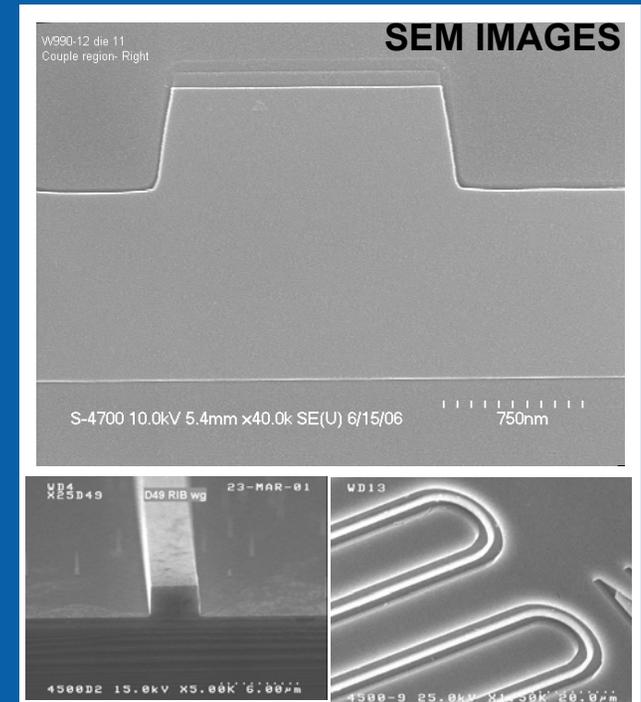
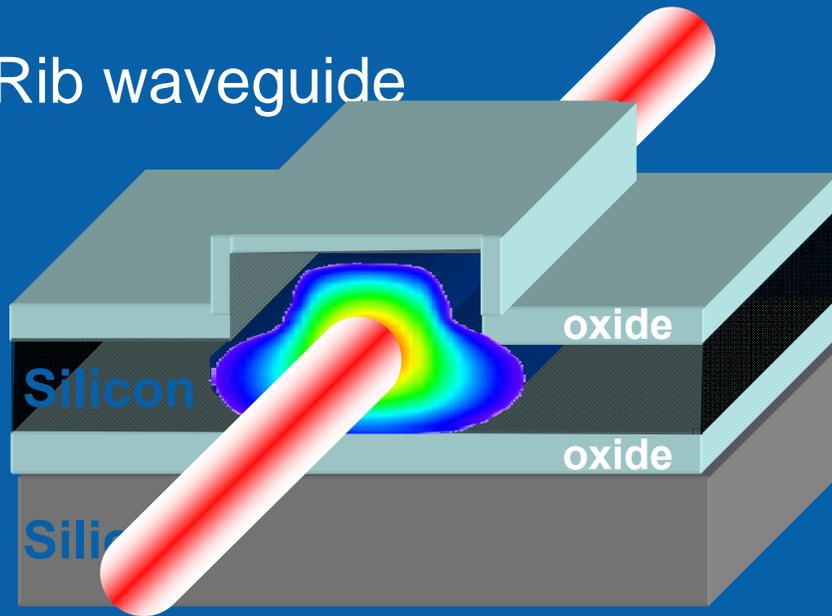


6) Intelligence



Guiding Light with Si Waveguides

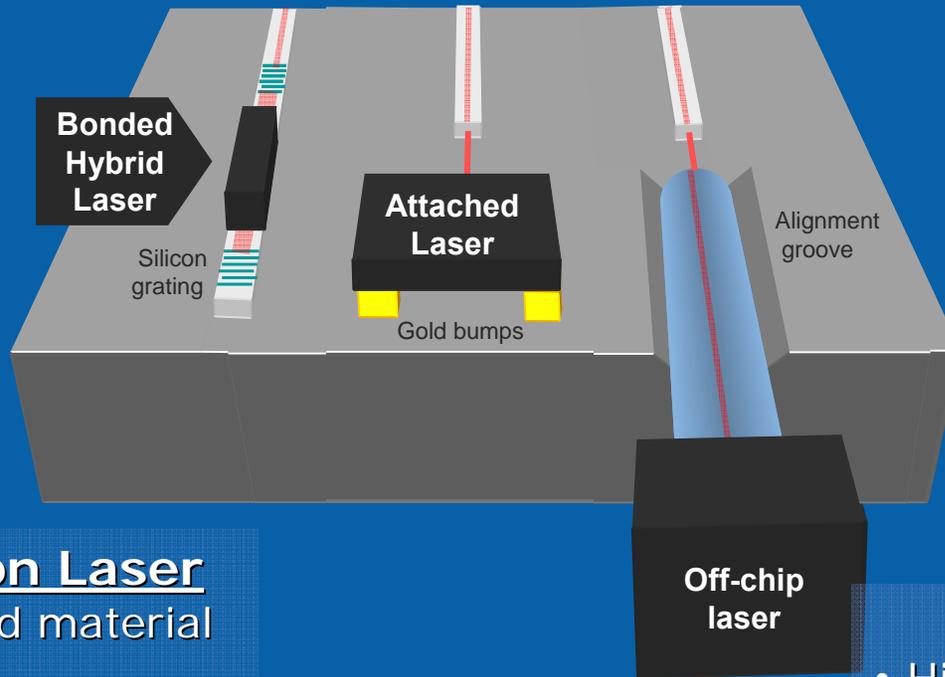
Ex: Rib waveguide



- Proven area for silicon
- High index = small structures
 - Strip and Photonic crystals for further scaling
- Splitters, couplers, gratings, AWGs, MMIs have all been demonstrated

Continue to reduce size while maintaining performance

Options for Integrating Light Sources



Hybrid Silicon Laser

- Bond InP based material to Silicon
- No alignment
- Many lasers with one bonding step
- Amenable to high integration
- Potentially lowest cost

Direct Attached Laser

- Tight alignment tolerances
- Requires gold metal bonding
- Passive alignment challenges
- Less Expensive

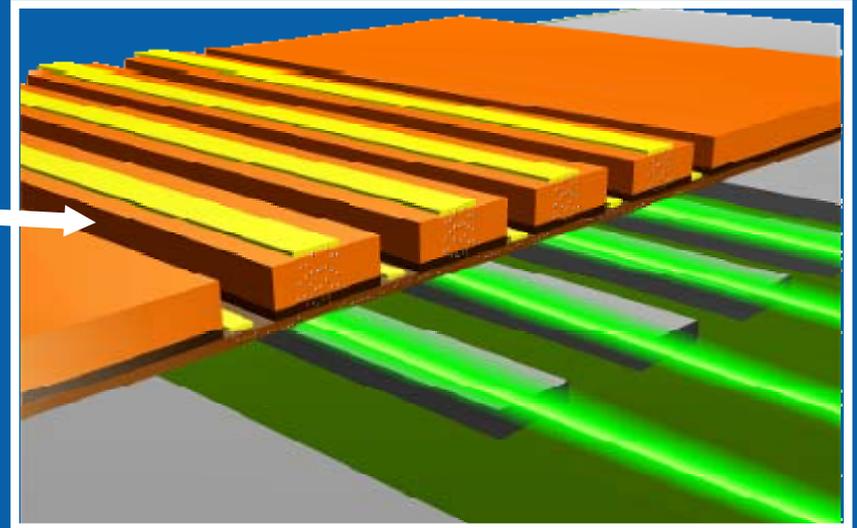
Off-chip Laser

- High power laser required
- Requires fiber attach
- Non-integrated solution
- Expensive

Hybrid Silicon Laser

Collaboration with UCSB

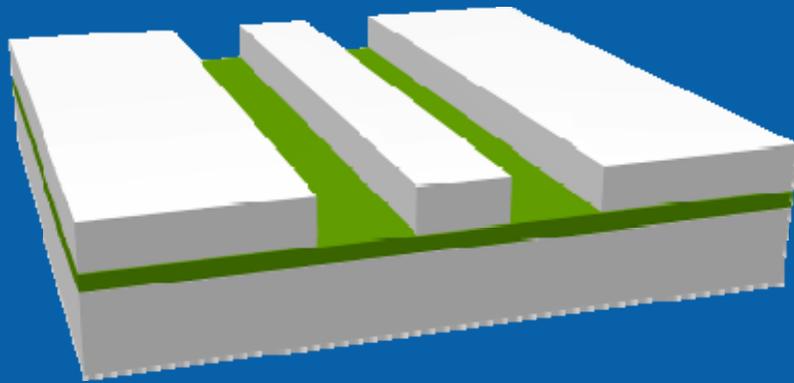
- The Indium Phosphide emits the light into the silicon waveguide



- The silicon acts as laser cavity:
 - Silicon waveguide routes the light
 - End Facets or gratings are reflectors/mirrors
 - Light bounces back and forth and gets amplified by InP based material
 - Laser performance determined by Silicon waveguide

No alignment needed
10's if not 100's of lasers with ONE bond

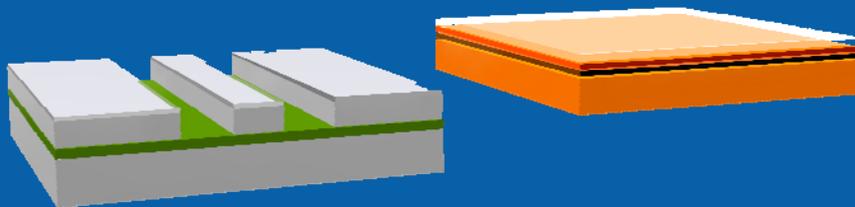
Hybrid Laser Process



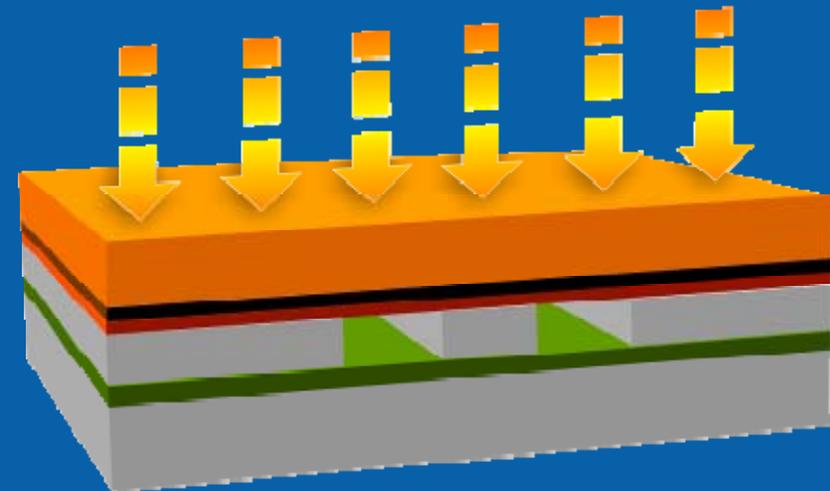
1) A waveguide is etched in silicon



2) The Indium phosphide is processed to make it a good light emitter



3) Both materials are exposed to the oxygen plasma to form the "glass-gue"

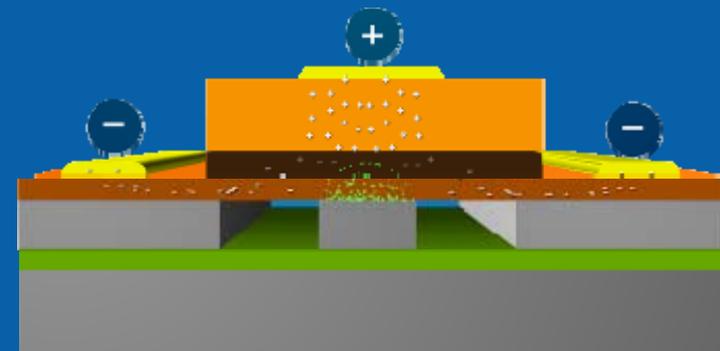


4) The two materials are bonded together under low heat

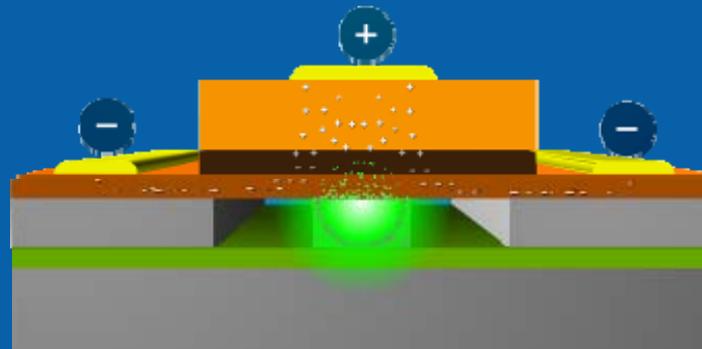
Hybrid Laser Process



5) The Indium phosphide is etched and electrical contacts are added

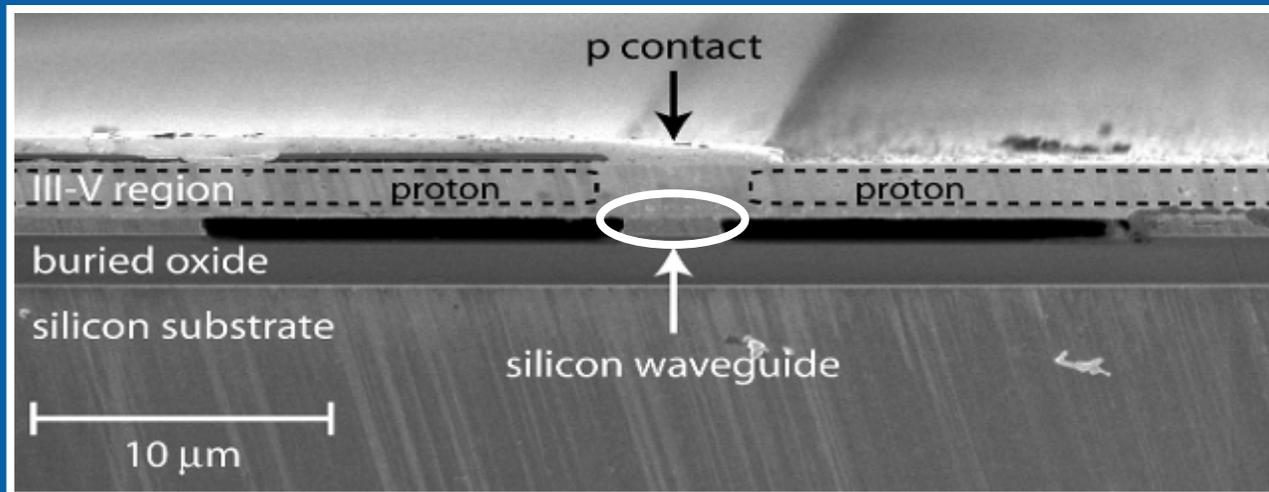
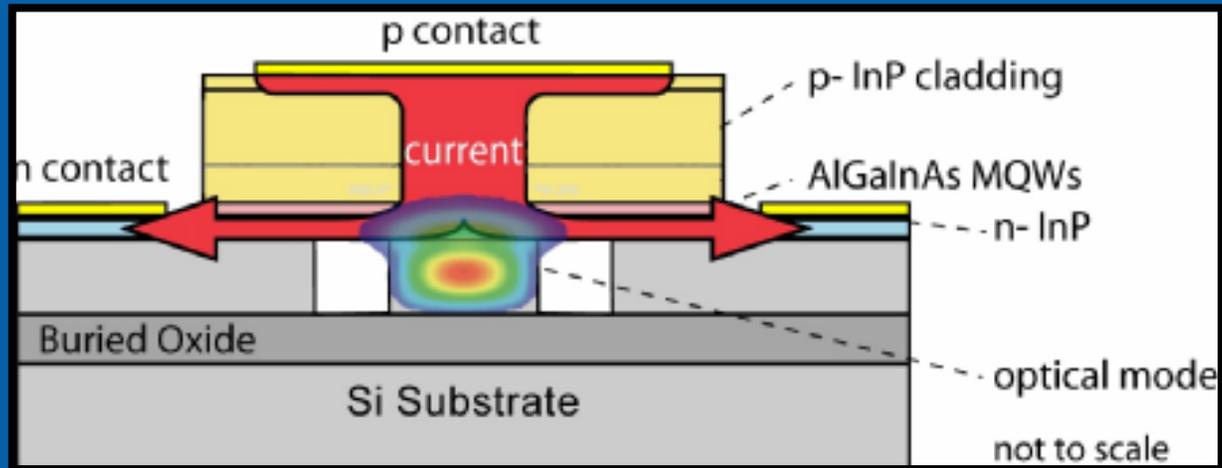


6) Photons are emitted from the Indium Phosphide when a voltage is applied



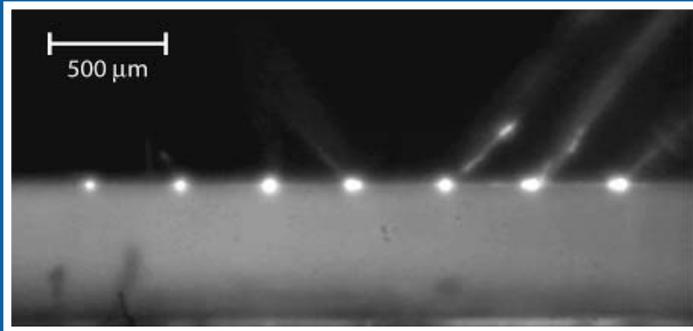
7) The light is coupled into the silicon waveguide which forms the laser cavity. Laser light emanates from the device.

Hybrid Laser Structure

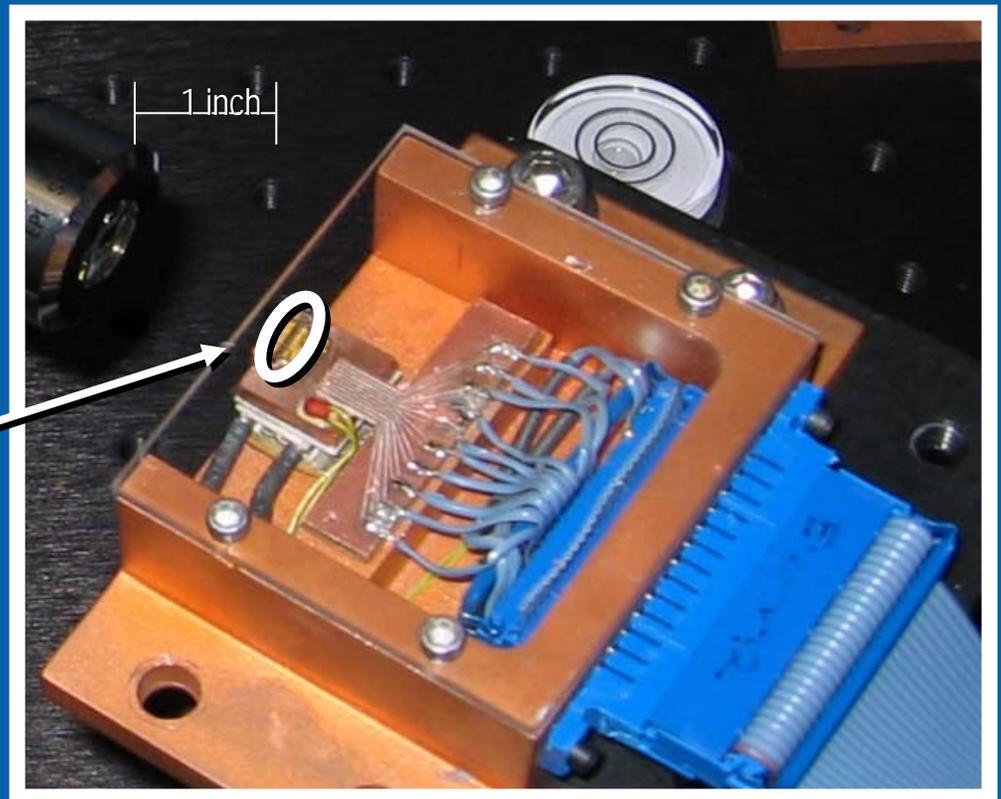
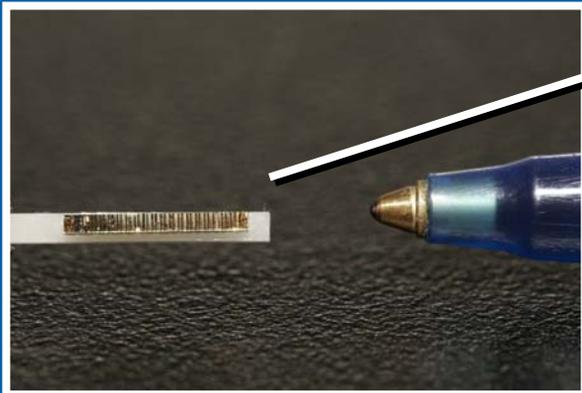


SEM (Scanning Electron Microscope) Photograph

Silicon Hybrid Laser



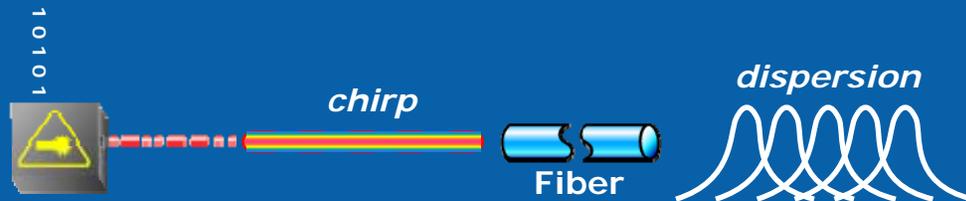
7 lasers outputting simultaneously



Modulation

- Direct or External modulation
- External used for 10G at ~12km+

Direct Modulation



Data rate limited

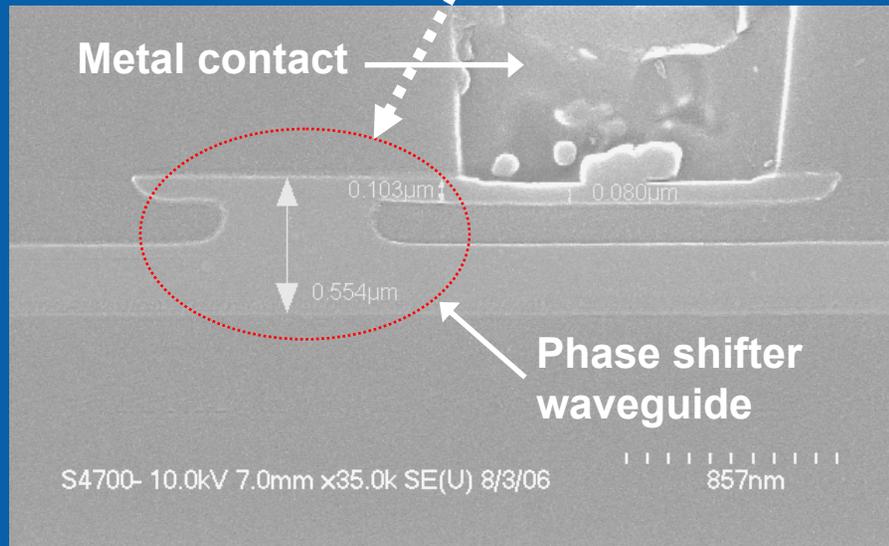
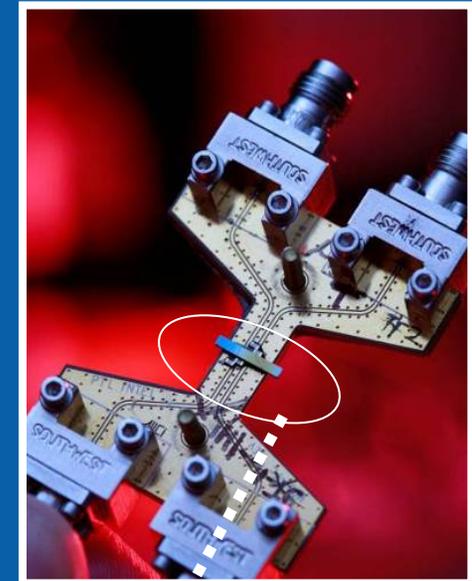
External Modulation



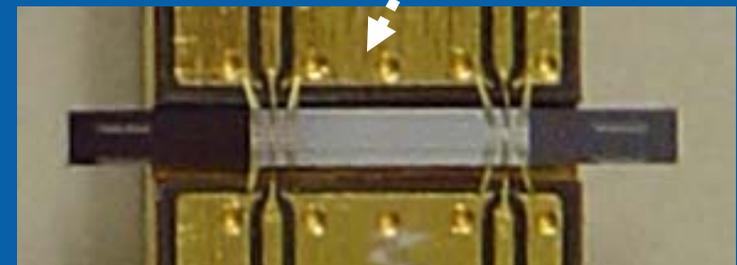
Very \$\$\$

No electro-optic effect
use free carriers

Intel's Second Generation: Silicon Modulator

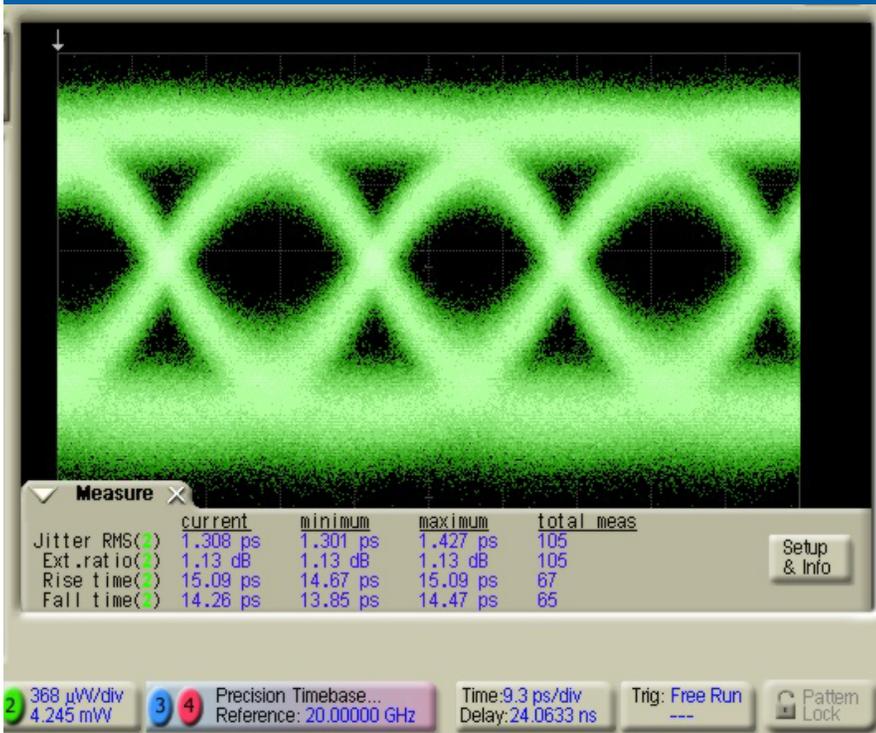


SEM picture of p-n phase shifter

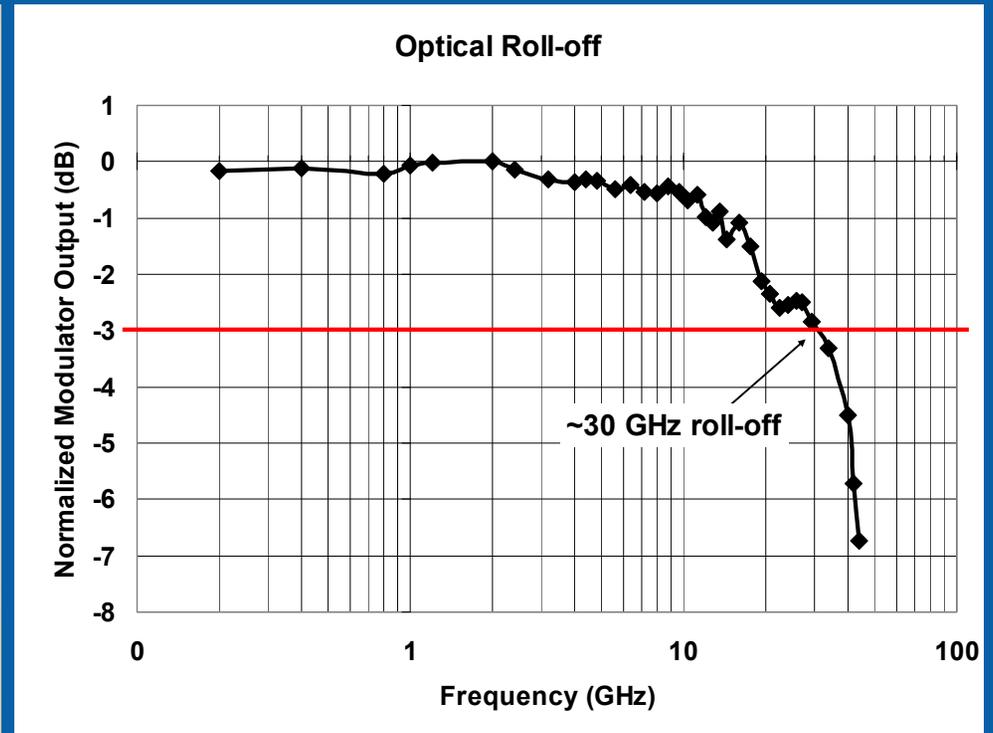


- Based on traveling wave design
- Optimized optical & electrical RF

Recent Results: 40Gb/s Data Transmission



40Gb/s Data Transmission

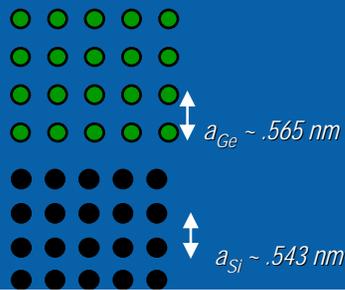


Optical 3 dB roll off ~30 GHz

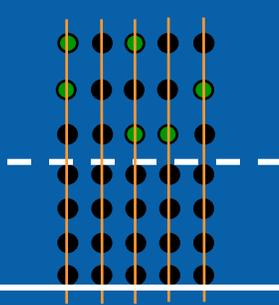
Photodetection

- Silicon does not absorb IR well
- Using SiGe to extend to $1.3\mu\text{m}+$
- Must overcome lattice mismatch

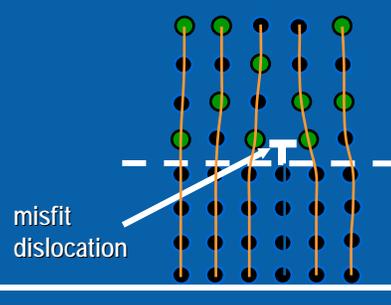
Bulk Films of Si and Ge



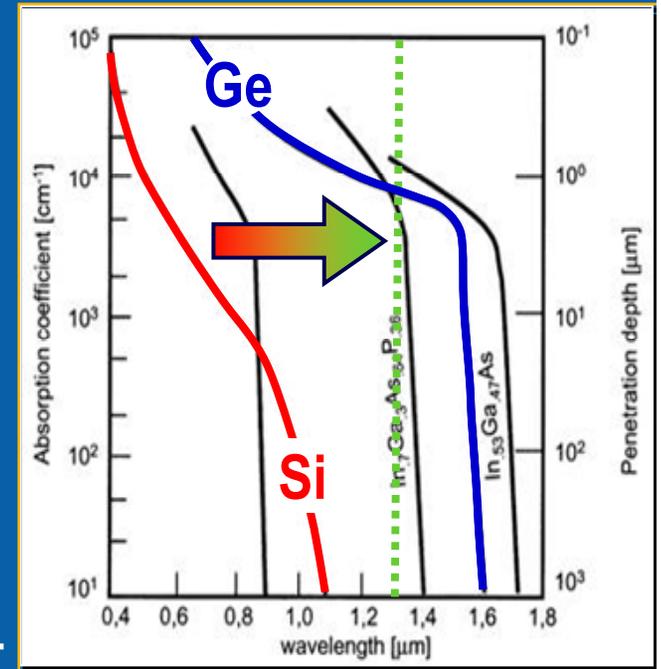
Strained $\text{Si}_{1-x}\text{Ge}_x$ on Si



Relaxed $\text{Si}_{1-x}\text{Ge}_x$ on Si

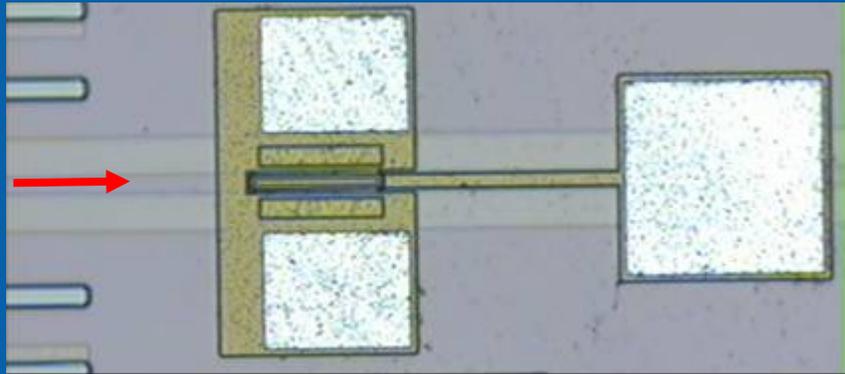


Misfit dislocations typically create threading dislocations which degrade device performance - dark current (I_{dk}) goes up.

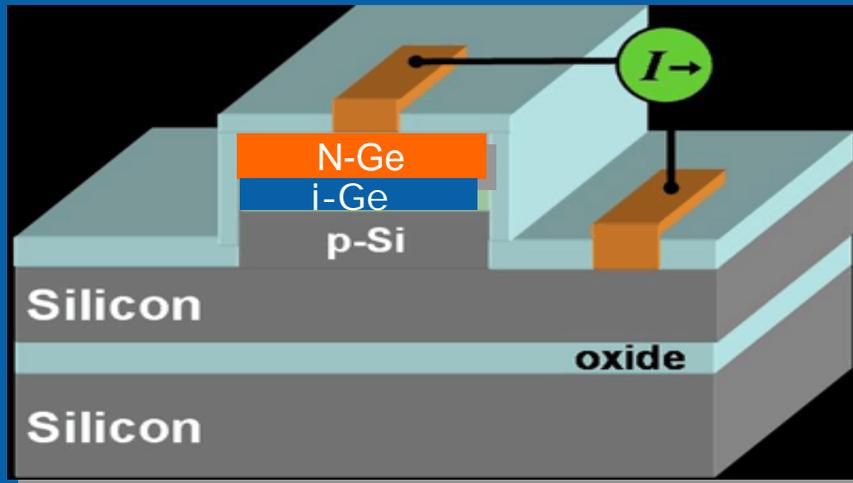


Must simultaneously achieve required speed, responsivity, & dark current.

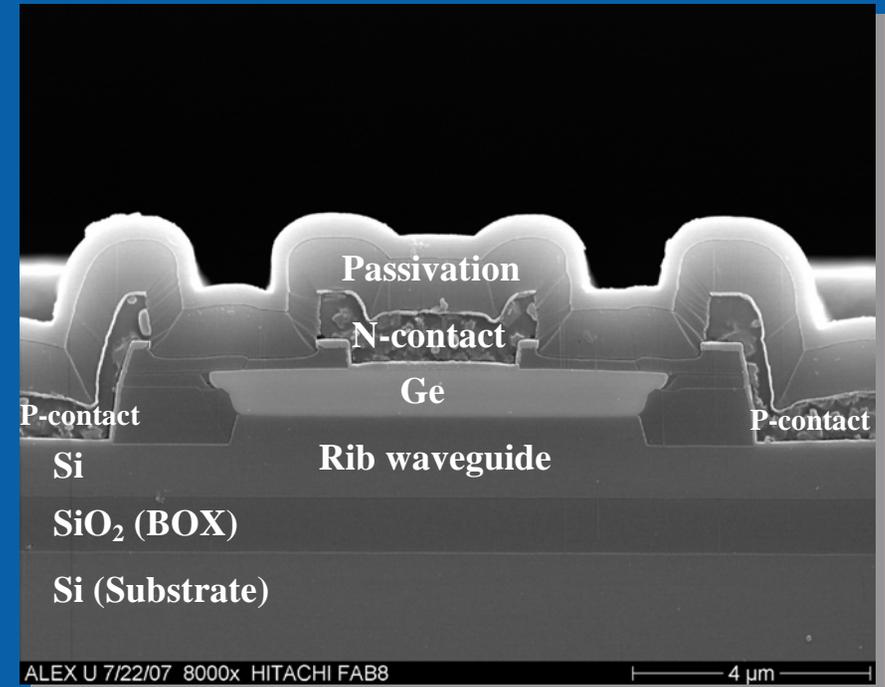
Waveguide Photodetector Design



Top View



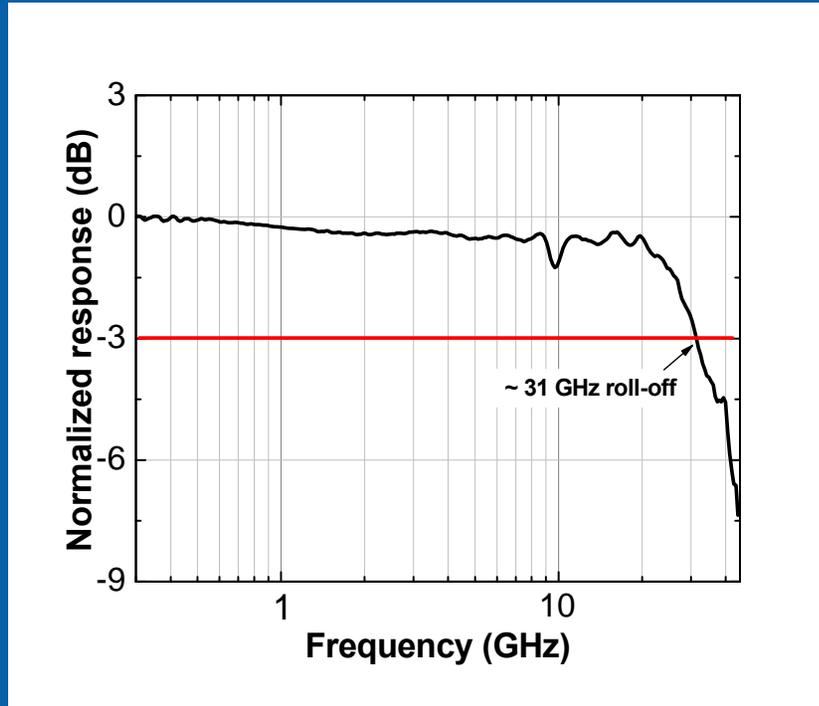
SEM Cross-Section



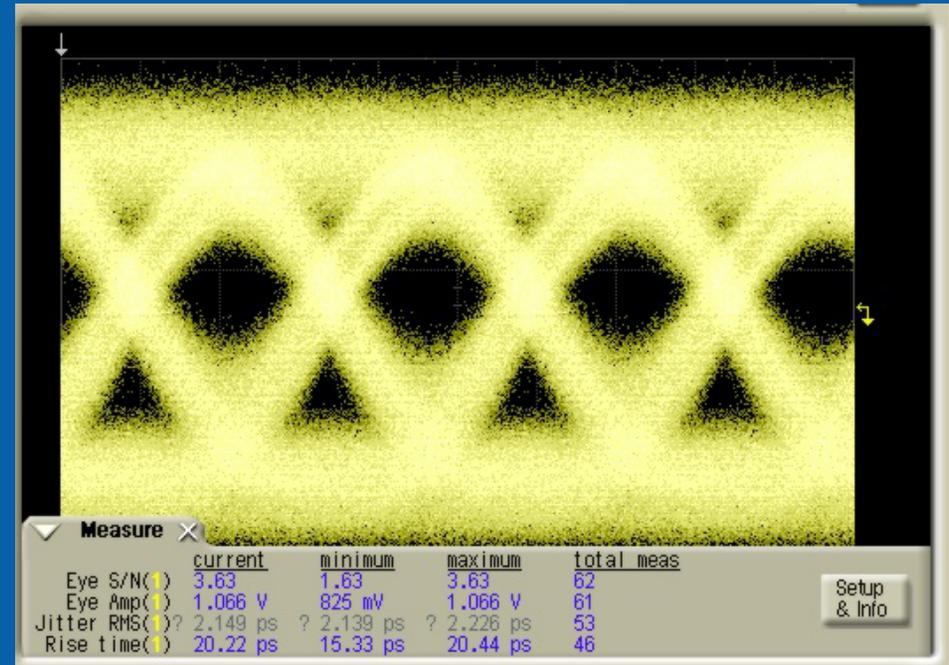
SEM Cross-Section

Experimental Results: 40Gb/s

Presented Sept 20th: Group IV conference Tokyo Japan



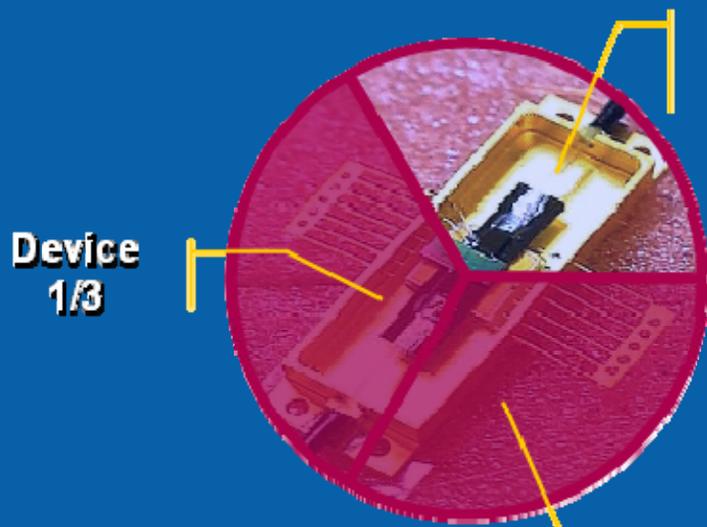
31 GHz Optical Bandwidth



40 Gb/s Data transmission

95% efficient (up to $\lambda \sim 1.56\mu\text{m}$)
< 200nA of dark current

Low Cost Assembly



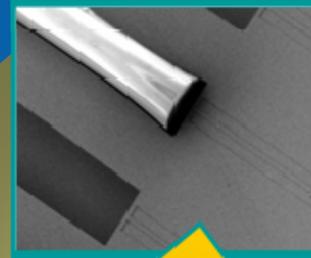
Device
1/3

Packaging
1/3

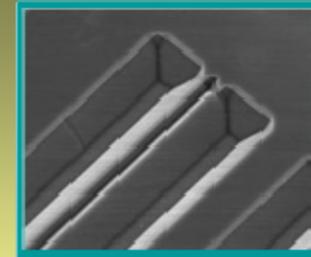
Testing
1/3

Use passive alignment
and lithographically
defined silicon
micromachining

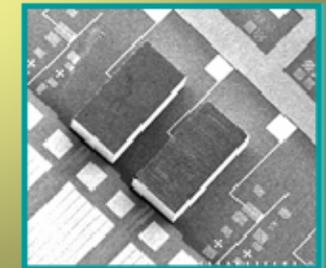
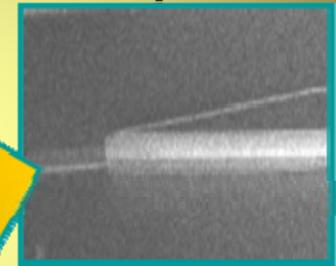
U-Grooves



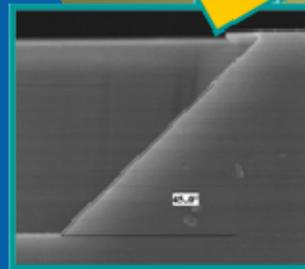
V-Grooves



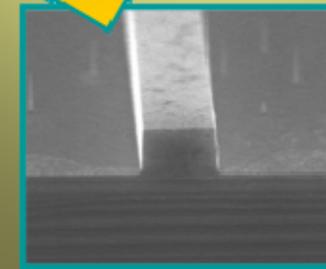
Tapers



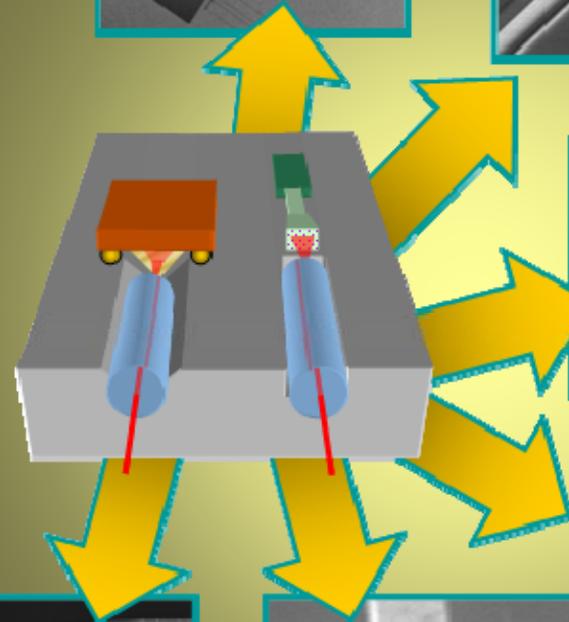
Laser Attach



45° Mirrors

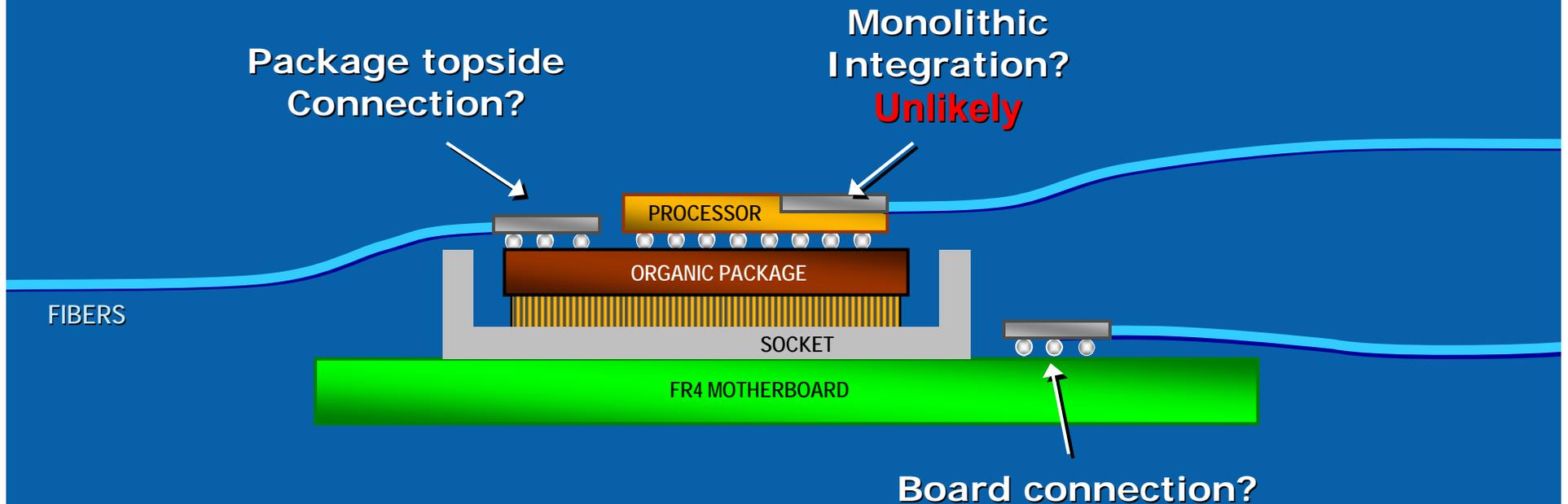


Facet Preparation



Challenge: Packaging

Example: Optical Interface

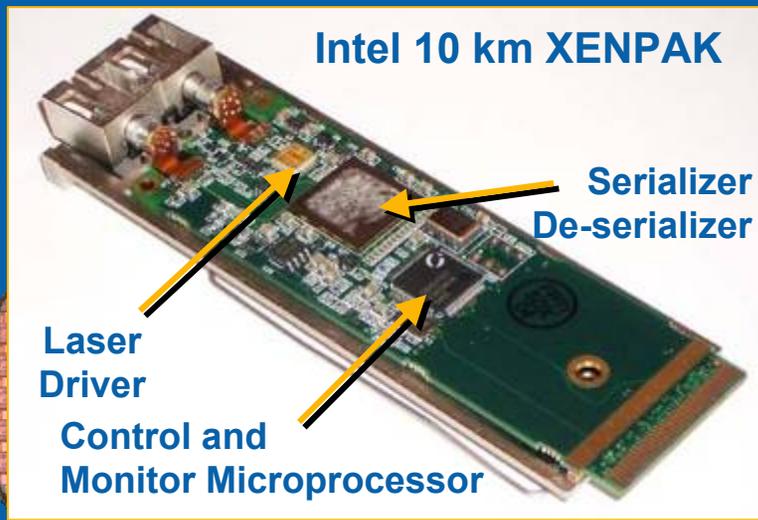


Issues: Connector cost, assembly cost, testing, reliability and compatibility with existing electrical packages

Multiple approaches. Must balance performance, flexibility and feasibility

CMOS Intelligence

- Electronics are needed to control photonics – no optical logic
 - Transimpedance & Limiting Amplifiers for photodetection
 - Drivers for lasers/modulators
 - Also Clock Data Recovery, Serializers/Deserializers, etc.



**Use hybrid attached
CMOS electronics.
Explore monolithic
integration over time**

Integration: Hybrid?

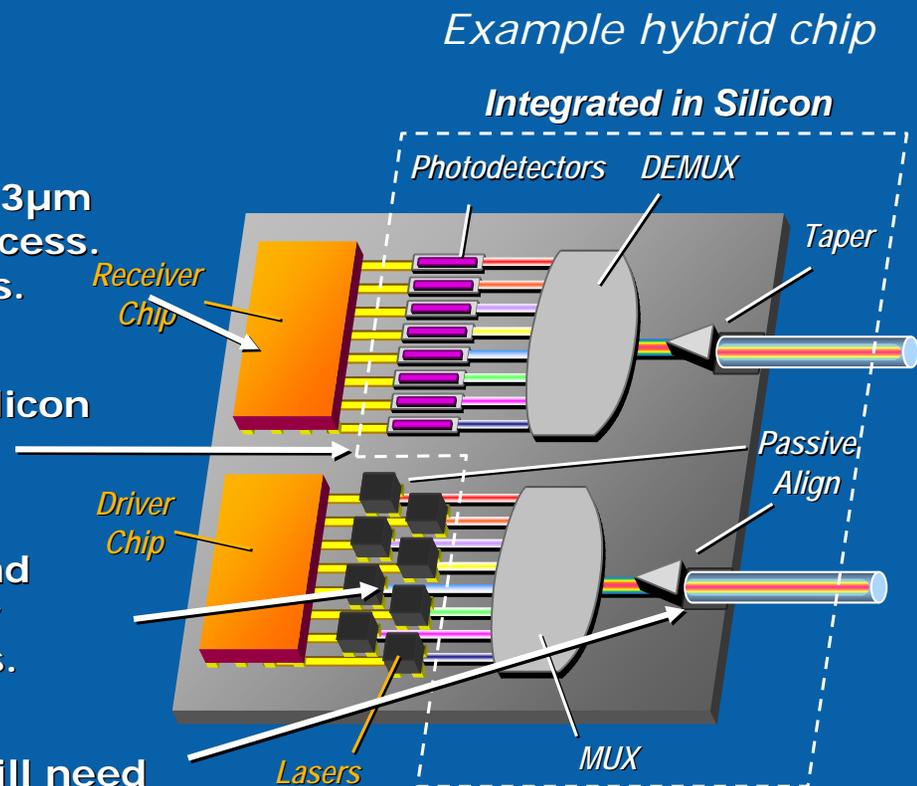
Photonics and electronics processed separately

10 Gbps electronics could use $< 0.13\mu\text{m}$ while optics may use older gen. process. Attachment via bumps or wirebonds.

Integration of passive and active silicon devices reduces assembly & cost.

External III-Vs: require coupling and alignment (vertical & horizontal) or direct wafer bonding to waveguides.

Both monolithic and hybrid chips will need to couple light to the outside world.



Hybrid will offer the best price-performance near term

Integration: Monolithic?

Photonics and electronics processed together on a single wafer

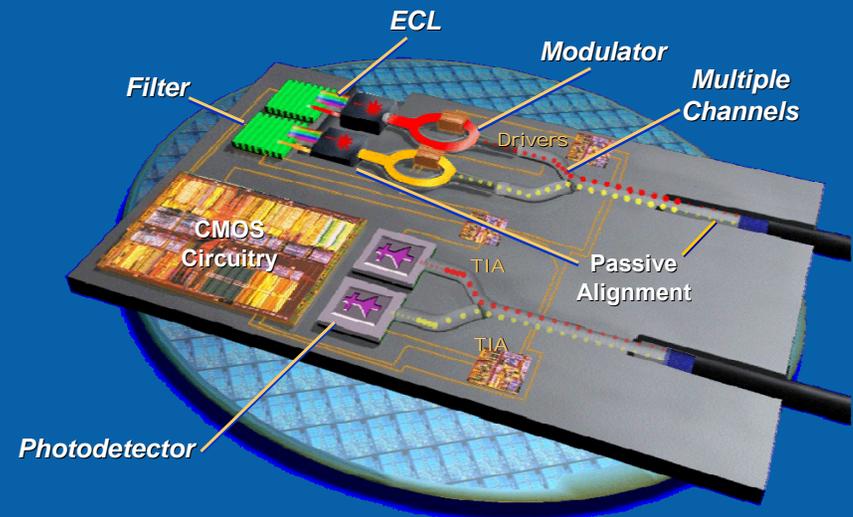
- **Motivations:**

- Performance, e.g. a Photodetector with a Trans-impedance amp
- Reduced form factor
- Cost?

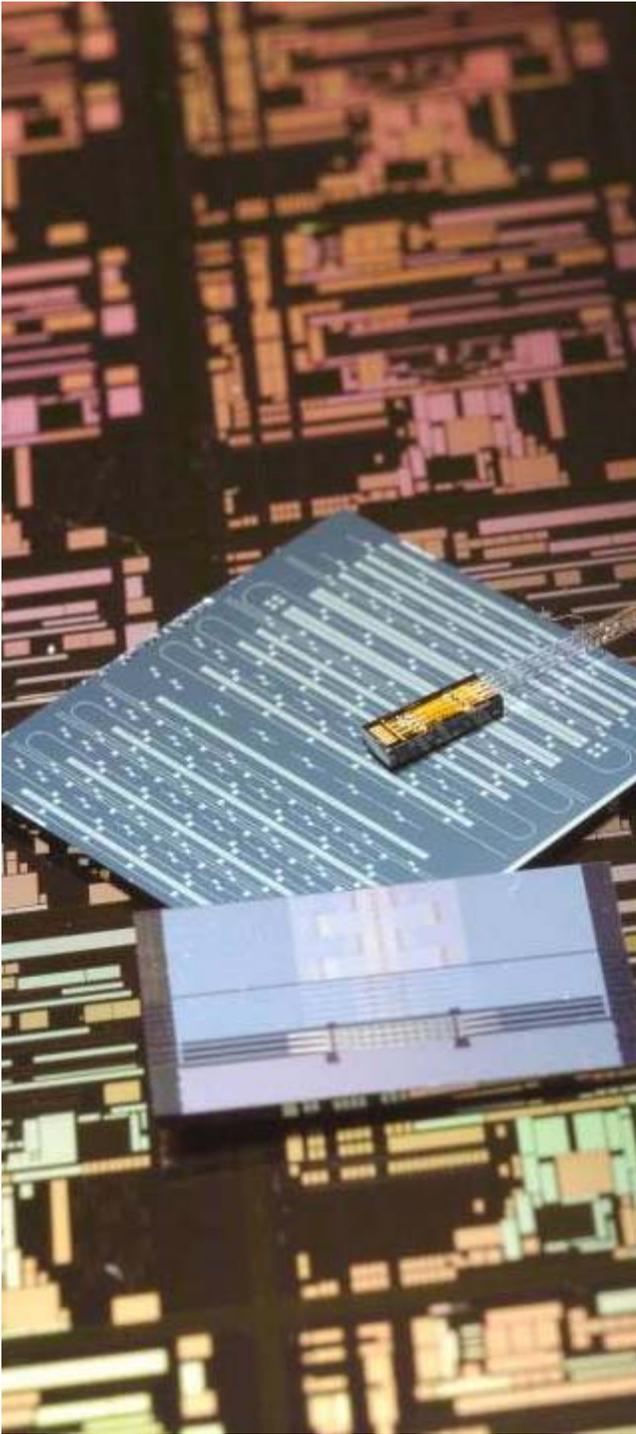
- **But many challenges** for achieving high yield:

Tighter thermal budgets, topology, metrology, complexity, etc.

Example monolithic chip



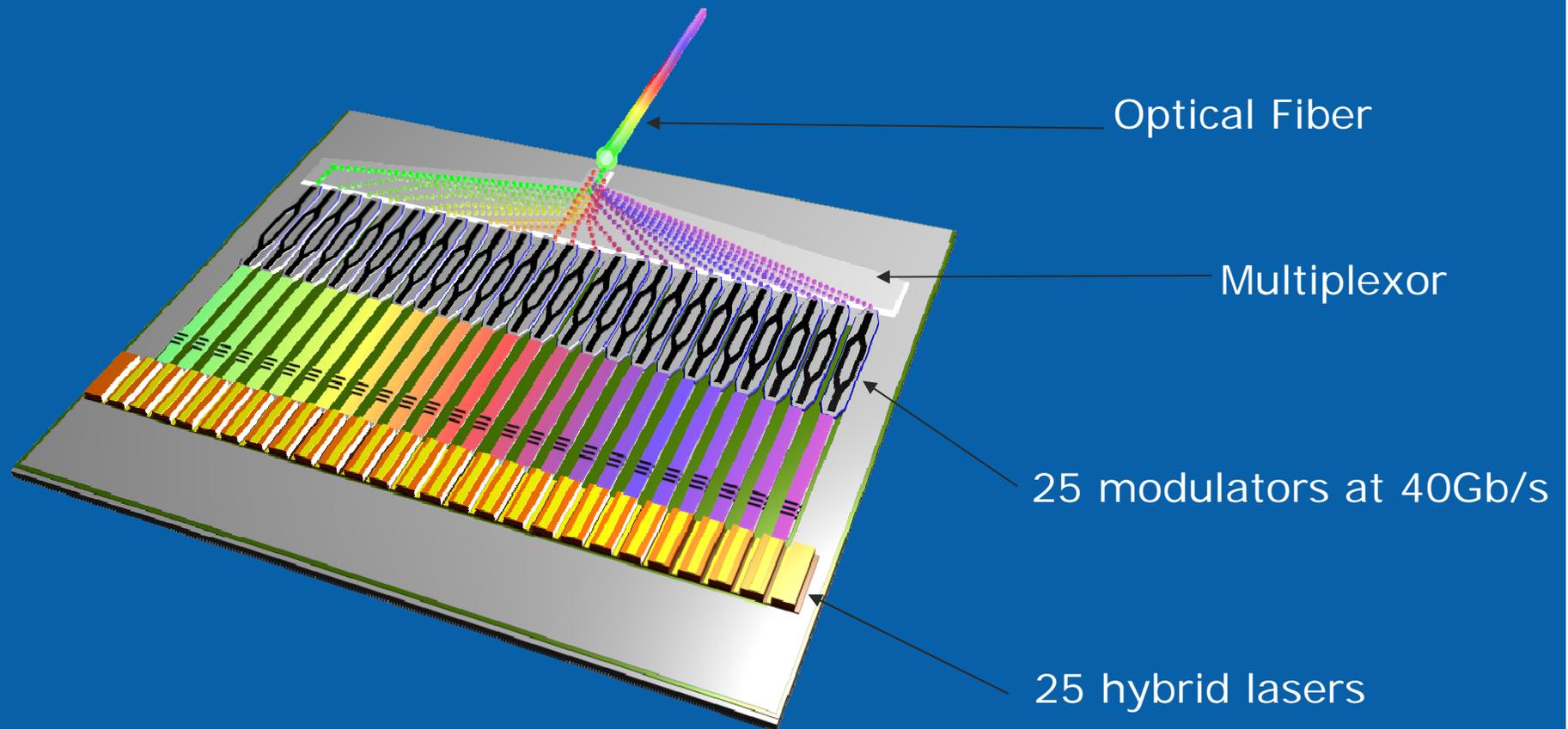
**Yield issues make monolithic
a longer term proposition**

A composite image showing various silicon photonic components. The background is a dense, colorful grid of microscopic structures. In the foreground, there are several larger, more detailed views of specific devices, including a blue waveguide structure with a small yellow component and a white waveguide structure with a small black component.

Silicon Photonics

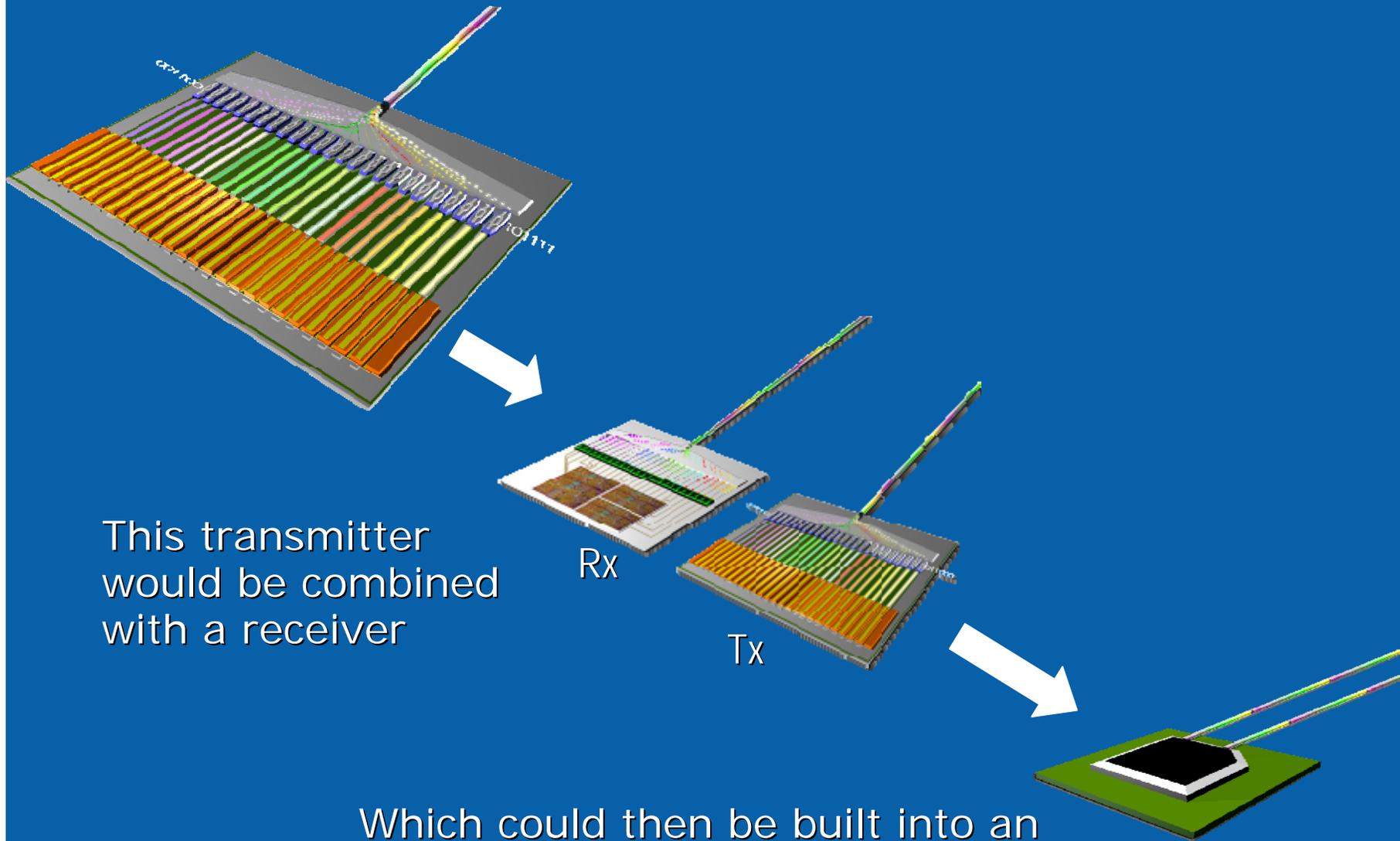
- Motivation & applications
- History & progress
- Intel's Research Program
- Future Work
- Summary

Where are we going?



An future integrated 1 Tb/s optical link
on a single chip

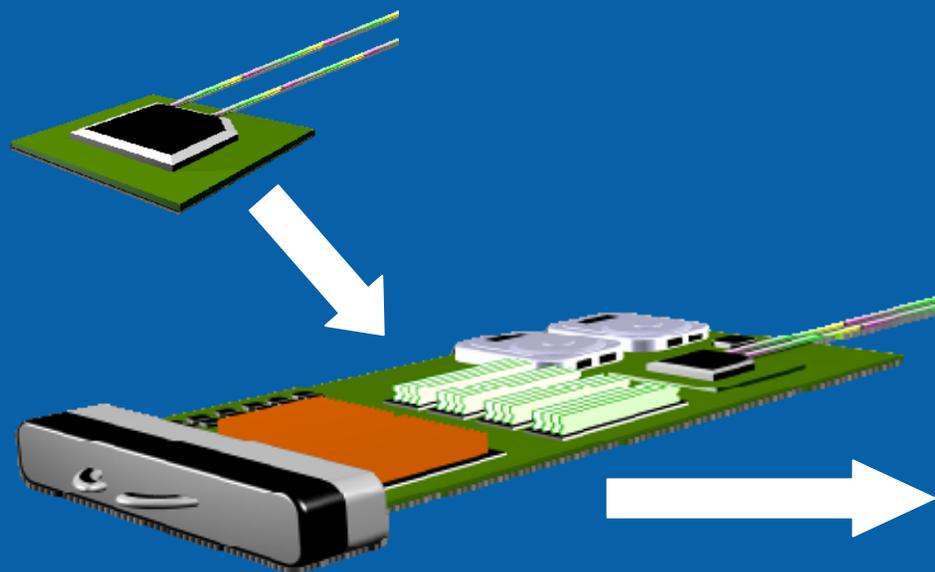
Integrating into a Tera-scale System



This transmitter would be combined with a receiver

Which could then be built into an integrated, silicon photonic chip!!

Integrating into a Tera-scale System



This integrated silicon photonic chip could then be integrated into computer boards



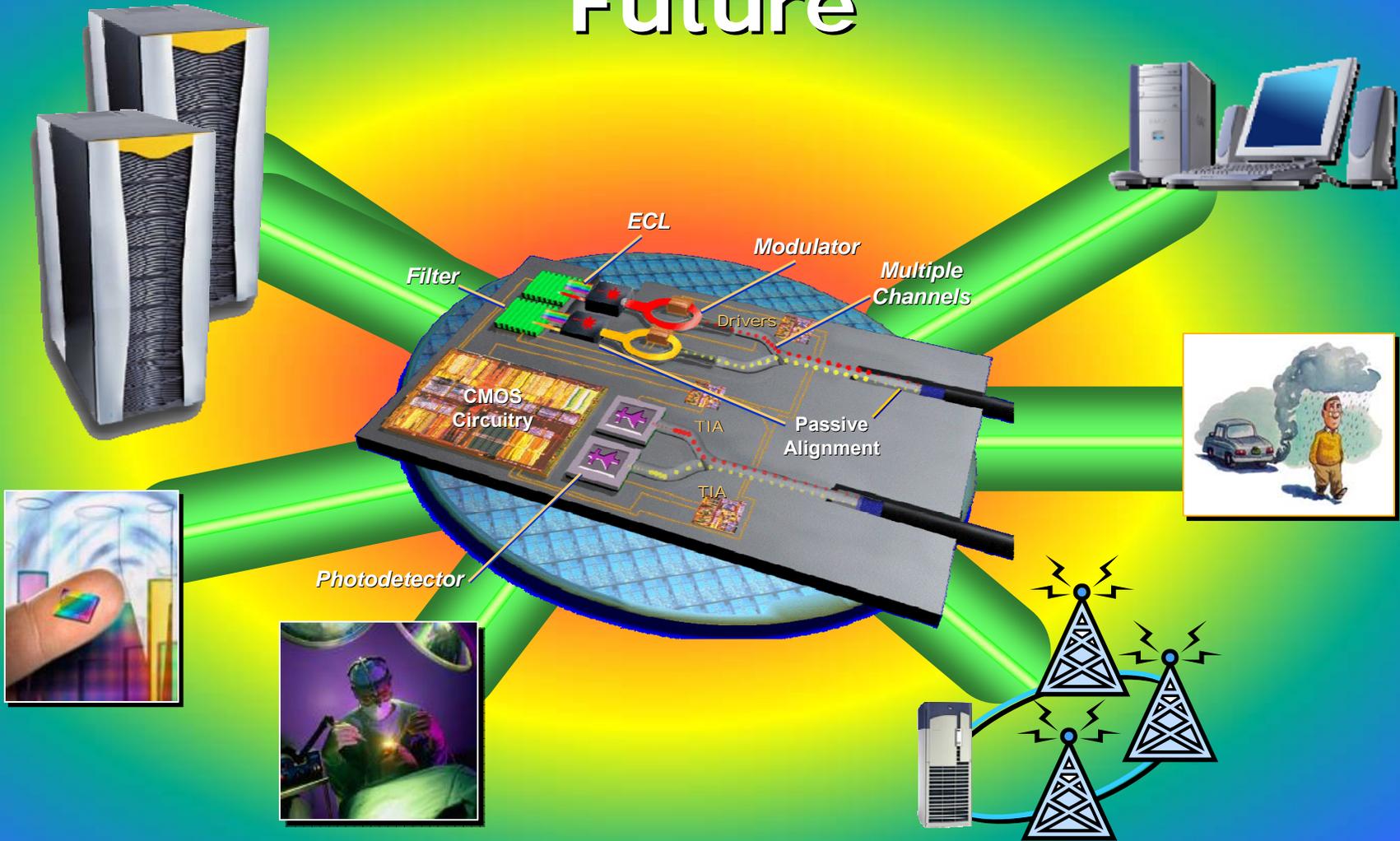
And this board could be integrated into a Tera-scale system

Summary

- Long term, convergence opportunities will be in silicon
- Silicon photonic device performance advancing at an accelerated pace.
 - Need to continue to push performance (i.e. 40G, 100G...)
- Next phase of challenges will be with integration.
- For interconnects, need to optimize electronics & photonics
 - Packaging, power, signaling, and cost will be key

If successful volume economics could allow silicon photonics to impact many areas from communications to bio to medicine

Silicon Photonics' Future



www.intel.com/go/sp